

AUXILIARY ENGINE DIGITAL INTERFACE
UNIT (DIU)

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SYSTEM DEVELOPMENT
COMMUNICATIONS
DATA LINK
DATA PROCESSING
ANTENNAS
MULTIPLEXERS

ST. PETERSBURG, FLORIDA

AUXILIARY ENGINE DIGITAL INTERFACE

UNIT (DIU)

CONTRACT NO. NAS8-27323

Prepared for

NATIONAL AERONAUTICS AND SPACE ADMINISTRATION

GEORGE C. MARSHALL SPACE FLIGHT CENTER

HUNTSVILLE, ALABAMA 35812

FINAL REPORT

AUGUST 1972

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**AUXILIARY PROPULSION SYSTEM/
DIGITAL INTERFACE UNIT
(APS/DIU) BREADBOARD
FINAL REPORT**

1.0 INTRODUCTION

On April 27, 1971, ECI was contracted to design, fabricate and test an Auxiliary Propulsion Engine Digital Interface Unit oriented for application on the Space Shuttle. This unit controls both the valving of the fuel and oxidizer to the engine combustion chamber and the ignition spark required for timely and efficient engine burns.

In addition to this basic function, the unit is designed to manage its own redundancy such that it is still operational after two hard circuit failures. Further, it communicates to the data bus system several selected information points relating to the operational status of the electronics as well as the engine fuel and burning processes.

The system design represents a significant advance in the state-of-the-art of digital systems for NASA in that it proves out the feasibility of implementing Complementary MOS circuitry both in discrete form or LSI form within the Shuttle vehicle control systems. In addition, this implementation typically demonstrates the level of complexity required to acquire subsystem dual-failure immunity.

2.0 DESIGN PHILOSOPHY

The underlying philosophy behind the circuits designed for the APS/DIU is that they easily be implemented into CMOS LSI with a minimum of documentation alterations. Several breadboard modules, in this case, could be incorporated within a single LSI chip where the two prime considerations are device density and I/O requirements.

This philosophy creates complexity in a breadboard system that would not otherwise be required if the system were merely constructed with discrete logic or passive components. For example, a seven input NAND function is a simple part within a LSI chip and the addition of three inputs to a four input NAND layout occupies very little



real estate. However, a seven input gate was not available in CMOS during the fabrication of this breadboard and had to be constructed from several devices. This occupies quite a bit of breadboard real estate and is costly in that the excess gates within the packages required to create the function are not always useful at the given location.

To minimize this costly approach, the breadboard was fabricated of pure CMOS where timing and propagation considerations were of a critical nature. Here, the function may be transferred directly to a LSI configuration with little or no logic alterations. An example of these designs are found in the Input Supervisory Validity Comparison and Status Monitor Circuits.

Alternately, where timing and propagation delays are not considered critical, discrete components are used to compliment the use of additional logic thereby reducing complexities and cost. Several examples of this will be demonstrated in this report. Functionally, the designs with discrete components perform identically to the pure logic form desired.

3.0 AUXILIARY PROPULSION ENGINE DIGITAL INTERFACE UNIT ELECTRICAL DESIGN

3.1 SUMMARY OF ELECTRICAL DESIGN

The purpose of this breadboard has been to:

- (1) verify the feasibility and operational complexity of an APS/DIU capable of dual-failure immunity
- (2) verify the feasibility and performance parameters of Complimentary MOS logic in performing this function.

3.1.1 Functional Complexities

To complete these tasks, the circuits were fabricated using CMOS on plug-in cards which were rack-partitioned within a commercial bench style cabinet. The circuits were partitioned both according to module function as well as a redundant function. Here,



interchangeability is maintained as universal as possible for performance evaluation and troubleshooting. Where simplicity dictated that a specific function and its redundant counterparts should be mounted on the same module, it was done so. Here, testing and observation can be accomplished by placing the card on an extender card.

Each module is powered in accordance with the partitioning of the redundancy scheme. That is, for example, Line Receiver "A" in position "A" is powered by "A" power supply. It would be, however, capable of performing in the Line Receiver "B" position in which case it would become Line Receiver "B". Exceptions to this arrangement are found on certain modules where single-failure majority voting is accomplished. Here, the power supplies are "ORed" to preempt a prime power failure reducing the majority voting capability.

The module back plane wiring uses a point-to-point scramble scheme intended to reduce cross-coupling capacity between signal paths. The power wiring is the only shielded wiring in the system and the shields are intended to reduce the coupling from the current-carrying lines to the high-impedance signal lines. Because the system is a breadboard by definition, no attempt to create cables was made since their formation would, in most probability, be detrimental to the system performance.

The architecture of the system breadboard is, at best, a very poor representation of an LSI type construction. The signal paths, for instance, are measured in feet instead of mils as would be the case on a chip. Nevertheless, if the devices perform the functions desired within this architecture, obviously the design would operate in an LSI configuration. A computer verification of the shorter propagation delays in the LSI layout is all that is required to confirm nominal operation. In addition, the breadboard architecture offers a circuit exposure to radiant noise that most certainly would not exist in the LSI format. Again, the natural immunity of the circuit designs to noise problems is demonstrated and assured to improve in the conversion to LSI.

The philosophy of dual-failure immunity would include not only active device redundancy but signal path redundancy to protect against such failures as broken wires or failed



connectors. The breadboard does not include the signal path redundancies. The thinking here was that the signal path wiring redundancy would do nothing to verify the functional redundancies of the logic and would merely complicate the logic boards and back-plane system. And, the multitude of additional redundant wiring would not necessarily be representative of the signal paths within an LSI system due to the partitioning of the breadboard. Broken wires, failed solder or wirewrap connections or interrupted connector connections should be relatively easy to locate and repair within the breadboard should they occur.

3.1.2 Performance of CMOS Logic

Within the architecture discussed, the CMOS logic devices selected performed well beyond ECI's expectations. Because they are very high impedance devices, we had expected to witness rather severe noise pickup from sources different from the APS/DIU as well as internal crosstalk and interference. This did not happen, in spite of the fact that virtually all of the signal lines within the breadboard are excessive in length. The system frequency limit is just about two megahertz because some pulse shape deterioration was witnessed at these frequencies. This deterioration, however, was not severe enough to inhibit the desired performance.

Perhaps the most severe problem that has existed in the application of CMOS was the difficulty in turning it off. Because of the input protective diode network, the logic will perform its natural function with the presence of an input signal. Here, the input signal will provide power for the logic Vcc while not deteriorating the quality of the signal pulse characteristics. Now, to test a specific logic function where several similar functions are in parallel to provide the redundancy, the obvious method would be to power down the logic functions in sets and verify that the remaining sets still perform as expected. Disconnecting power does not work in this case. Instead, the input circuits had to be resistively isolated and the power lines of the specific function pulled to ground. The resistive isolation was such that it did not load the desired inputs to the active redundant circuits.



An alternate method that resultantly was not ideal for the breadboard, was to open the signal inputs with logic switches. Here, each input (signal, clock, etc.) would have to have a series switch to interrupt signal and a parallel switch to commit the opened input. This method, although feasible, is not practical. The switches increase cost, complexity plus add a series element subject to failure.

Re-evaluation of this method will be conducted, however, for an LSI fabrication to assess its impact on reliability and cost. On a LSI chip, only the inputs would necessarily have this network whereas on the breadboard every input-per-package is protected.

3.2 SYSTEMS FUNCTIONAL DESCRIPTION

This section describes the operation of the APS/DIU as depicted in the Functional Block Diagram, Figure 1.

The data inputs to the APS/DIU from a Data Terminal which communicates with the vehicle data bus. The format of this information is 20 bits Polar RZ with the 20th bit missing for word synchronization. The frequency is 1 MHz or 1 μ sec/bit.

3.2.1 Input Data Validity Comparison

The input line receivers accept this data from four separate but identical Data Terminals. The "ones" and "zeros" are separated at the input to each line receiver and a set of photo-isolators are fed separately. The secondary of the line receivers recovers this isolated data and feeds corresponding serial voters. Here, the 1's (or 0's) are combined bit-by-bit in a Serial Voter to eliminate any two faulted lines and output the correct data on all four lines to four registers. As shown in the figure, both the 1's and 0's are processed into storage separately. The detected "end-of-word" is used to load each new word.

From parallel storage, then, the information is parity checked and decoded and feeds the Majority Voter Summers, one for each command. There is one Majority Voter

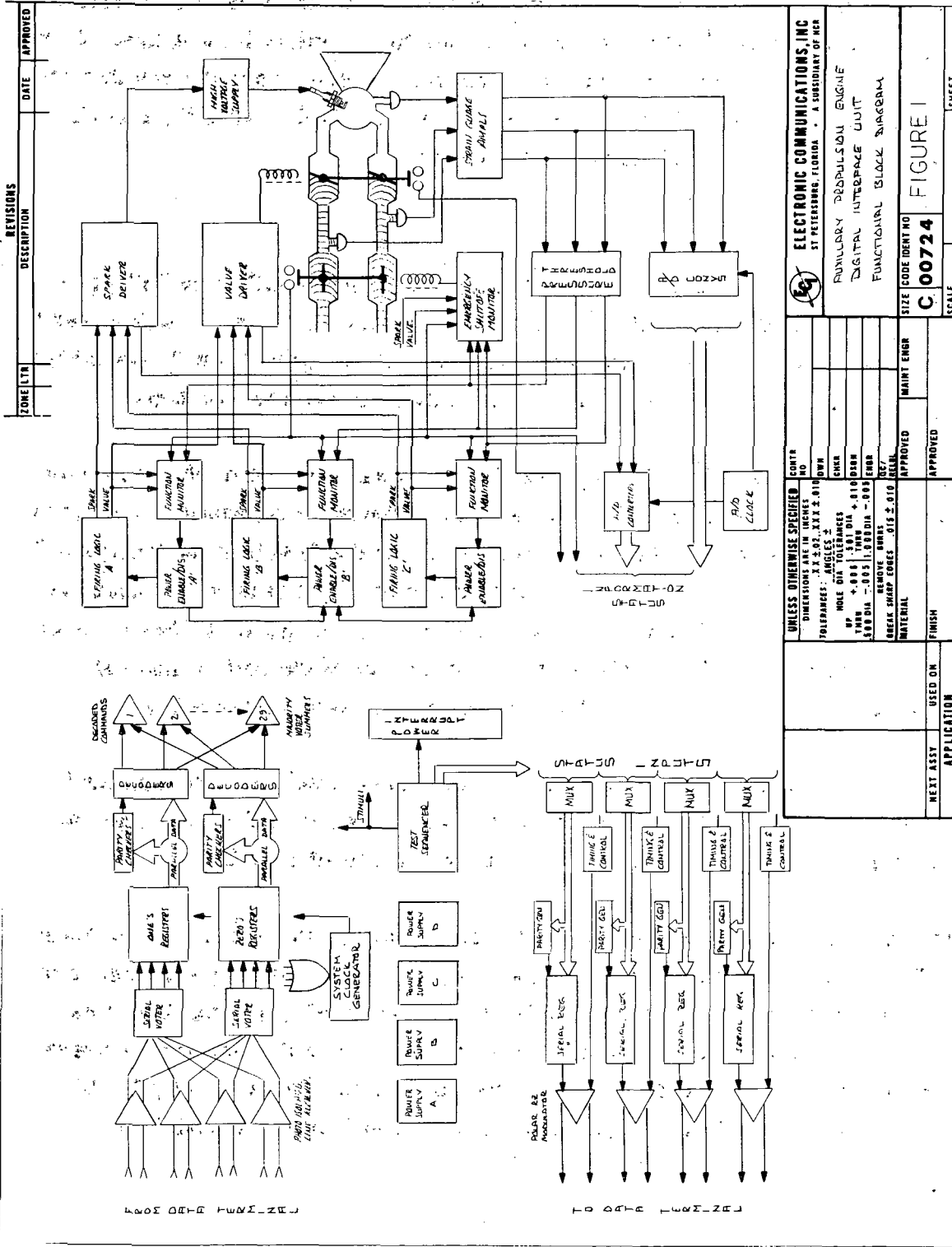


FIGURE 1. AUXILIARY PROPULSION ENGINE DIGITAL INTERFACE UNIT FUNCTIONAL BLOCK DIAGRAM

ELECTRONIC COMMUNICATIONS, INC. ST. PETERSBURG, FLORIDA - A SUBSIDIARY OF NCR	
AUXILIARY PROPULSION ENGINE DIGITAL INTERFACE UNIT FUNCTIONAL BLOCK DIAGRAM	
SIZE	CODE IDENT NO
C	00724
FIGURE 1	
SHEET	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	
TOLERANCES: XX ±.02, XXX ±.010	
HOLE DIA TOLERANCES	
UP +.005 .010 DIA +.010 DIA	
DOWN -.005 .010 DIA -.005 DIA	
REMOVE BURRS	
RADIUS SHARP CORNERS .015 ±.010 RADIUS	
MATERIAL	
APPROVED	MAINT ENGR
APPROVED	APPROVED
NEXT ASST	USED ON
APPLICATION	



Summer for each bit and it is this circuit which combines all eight sets of information about a single command and outputs the correct state to a single redundant line. This feature eliminates any contradictions of redundant command paths and insures that any given command is sourced from a (virtual) single source. Table I lists the specific commands for the APS/DIU and their encoded format.

3.2.2 Firing Logic

The firing logic sections are configured in triplicate such that a failure in "A" automatically causes switchover to "B" and a failure in "B" causes automatic switchover to "C." The Firing Logic that is in use is the only one that is powered "on." The others are powered down until activated either automatically or by external command.

The system initiates itself into Firing Logic "A" at "power-on." And, it will remain there until it fails. If its failure mode is such that it cannot (or its associated drivers cannot) operate the valve, then the switchover will occur the first time an "engine-on" command is issued. If its failure mode is such that it attempts to issue an uncommanded "engine-on", then the switchover occurs immediately. Similarly, if "B" has an inert failure as described for "A", switchover to "C" will occur at the next "engine-on" command. Switchover is again immediate for an uncommanded engine burn.

A failure in Firing Logic "C" causes shutdown of the system until it is re-activated either by external command or the power is re-cycled. The system does not attempt to re-use a Firing Logic set that has previously been declared as failed.

The block diagram illustrates how each Firing Logic function is controlled by a Power Enable/Disable and a Function Monitor. The Function Monitor examines the states of the chamber pressure, input command, valve switches and valve and spark outputs from Firing Logic and determines whether the Firing Logic or its associated drivers are outputting according to command. When they do not, the Power Enable/Disable function powers down the faulted logic and causes "turn-on" of the next back-up.



COMMAND NO.	FUNCTION	CODE
1	Inhibit Firing Logics B & C (use A)	00001
2	Inhibit Firing Logics A & C (use B)	00010
3	Inhibit Firing Logics A & B (use C)	00011
4	Inhibit Chamber Pressure Ampl A	00100
5	Inhibit Chamber Pressure Ampl B	00101
6	Inhibit Chamber Pressure Ampl C	00110
7	Inhibit GH2 Pressure Ampl A	00111
8	Inhibit GH2 Pressure Ampl B	01000
9	Inhibit GH2 Pressure Ampl C	01001
10	Inhibit GO2 Pressure Ampl A	01010
11	Inhibit GO2 Pressure Ampl B	01011
12	Inhibit GO2 Pressure Ampl C	01100
13	(SPARE)	01101
14	(SPARE)	01110
15	Status: Pressure Threshold; Chamb, GO2, GH2	01111
16	Reset Override Commands	10000
17	Emergency Shutoff Command	10001
18	Engine Turn-On	10010
19	Engine Turn-Off	10011
20	Exercise "SELF-TEST" Program	10100
21	Status: Valve Driver A & B Current	10101
22	Status: Valve Driver C; Spark Driver A Current	10110
23	Status: Spark Driver B, Spark Driver C Current	10111
24	Status: GO2 Pressure Monitor 1 & 2	11000
25	Status: GH2 Pressure Monitor 1 & 2	11010
26	Status: GO2, GH2 Pressure Monitor 3	11010
27	Status: Chamber Pressure Monitor 1 & 2	11011
28	Status: Chamb Pressure 3; Firing Logics; Function Monitors	11100
29	Status: Spark Drivers; Valve Drivers; Valve Switches	11101

TABLE I. APS/DIU INPUT COMMANDS



3.2.3 Spark and Valve Drivers

Each Firing Logic set feeds two drivers, one for valve and one for spark. Each driver contains a "modulate" stage plus two stage of series inhibit to disable the driver in the event of two shorting failures. The three drivers within, for example, the Valve Driver are in parallel but operate singly with a given Firing Logic set. This is true also for the Spark Driver.

Both drivers are identical in structure and components with exception to the current-measuring resistors which restrict the Valve Driver to 50 ma output while the Spark Driver output is 1 ampere. This was intentionally done for this breadboard to demonstrate the versatility of the circuit and to provide for loads which were undefined during this program. It was assumed, therefore, that the valve would require 50 ma and the current-monitoring resistors would swing 0 to 1 volt for this load. Similarly, the spark was assumed to be 1 amp and the current monitor would also indicate 0 to 1 volt. These currents are continually monitored by A/D converters and can be accessed at any time for information reporting to the data bus system.

3.2.4 High Voltage Supply

The High Voltage Supply illustrated in the block diagram is for information purposes only in describing the system and is not part of the APS/DIU. This supply provides spark for the engine combustion chamber.

3.2.5 Emergency Shutoff Monitor

The function of this device is to close the additional valve shown in the event of a catastrophic failure not self-correctable by the APS/DIU. The monitor compares the chamber and line pressure thresholds, the spark and valve outputs from the drivers and the state of the valve switches. If there is an engine burn or a drop in pressure indicating that the line valves are, in fact, open without being driven open the Emergency Shutoff Valves are closed.



It should be noted that the Emergency Shutoff Monitor performs differently from the Function Monitors. The ESO Monitor seeks uncommanded and undriven engine reactions. The Function Monitors seeks faulty commands which were not dictated to the APS/DIU. The ESO monitor may cause shutdown of the Firing Logics depending on the conditions but the Function Monitors will never cause Emergency shutoff.

3.2.6 Strain Gauge Amplifiers

These amplifiers are analog interfaces with the pressure transducers located in the GH2 and GO2 fuel lines plus the engine combustion chamber. The original intent of the system design was that these amplifiers interface with redundant strain gauge pressure transducers. However, for purposes of this breadboard, at least, the triplex sets interface with a single transducer for each of the monitoring points. The breadboard is configured such that either configuration may be employed with minimum adjustment to the circuitry. In addition, each amplifier set is presently oriented to interface with a single strain gauge with the bridges configured on the breadboard. Alternate types of pressure transducers may be substituted by eliminating the bridge circuitry and re-scaling the amplifiers.

It is the function of these amplifiers to monitor the specific pressures at their designated points and report this information both to the threshold detectors and the A/D converters. Here, both the nominal performance and "graceful degradations" can be monitored.

3.2.7 Pressure Threshold Detectors and A/D Converters

The Pressure Threshold Detectors yield a binary "go, no-go" indication of the pressure status. Their intent is to permit the engine to be on-line and operational with some given degradation bounds. Outside of these bounds, the system will shut down.

The A/D Converters with 8-bit accuracy yield a continual measurement of the linear characteristics of these pressure measurements. Here, this information may be reported to the data bus (upon request) and analyzed for specific pressures nominal or degraded. In addition, there are A/D converters provided to monitor the



performance of both the Spark and Valve Drivers. As will be detailed later in this report, several items of information are yielded here, such as transistor leakage, etc., besides the measured "on" and "off" currents.

The converters employed are "tracking" A/D converters and 8-bits were selected to yield 0 to 5 V nominal scaling with 40 mv accuracy at the LSB. They may be accessed asynchronously at any time except during the 2 μ sec clocking period.

3.2.8 Status Monitor

The function of this section is to collect the status information from the A/D converters, various binary points such as the Power Enable/Disable circuits and the Test Sequencer and report it to the Data Bus Terminal upon request. Table I listed the input commands to the APS/DIU and of these, ten commands are status request commands including the self-test command. (See Table II.) These commands set up the Status Monitor Timing and Control function and adjust the multiplexers to view the requested information. The data is parallel loaded to the registers and serially shifted to the Data Terminal through the Polar RZ modulators 40 μ sec after the initial request.

The Status Monitor is a straightforward quad system with no intervening required. The system depends on the voting mechanisms at the Data Terminal to overcome any two failures that may occur in this area.

3.2.9 Test Sequencer

It is the purpose of the Test Sequencer to verify the internal redundancies of the APS/DIU and report these statuses to the data bus. It may be used as a "pre-flight" examination of the hardware or as a "diagnostic" in-flight test to determine what items have specifically failed such that manual redundancy override may be employed to re-configure the system to a possible operational configuration.

Once the APS/DIU has received a "self-test" command, it is inhibited from performing any normal functions until the test sequence is completed. The sequencer then verifies



BIT		STATUS REPLY WORD																			
CMD	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1		
20	0		FUNCTION MONITOR PERFORMANCE REDUNDANCY				STRAIN GAUGE AMPLIFIERS		CHAN.D.		CHAN.C	CHAN.B	CHAN.A	CONDITION OF VALVE & SPARK DRIVERS C SET B SET A SET Level 2 Level 1 Level 2 Level 1 Level 2 Level 1						1	
15	0		0	0	0	0	0	0	0	GO ₂ LINE PRES. THRESHOLD C B A			GH ₂ LINE PRES. THRESHOLD C B A			CHAMBER PRESSURE THRESHOLD C B A			1		
21	0		VALVE COILD DRIVER B CURRENT MSB LSB								VALVE COIL DRIVER A CURRENT MSB LSB								1		
22	0	PARITY (ODD OVER ALL 19 BITS)	SPARK IGNITER DRIVER A CURRENT MSB LSB								VALVE COILD DRIVER C CURRENT MSB LSB								1		
23	0		SPARK IGNITER DRIVER C CURRENT MSB LSB								SPARK IGNITER DRIVER B CURRENT MSB LSB								1		
24	0		GO ₂ LINE PRESSURE (MONITOR 2) MSB LSB								GO ₂ LINE PRESSURE (MONITOR 1) MSB LSB								1		
25	Q		GH ₂ LINE PRESSURE (MONITOR 2) MSB LSB								GH ₂ LINE PRESSURE (MONITOR 1) MSB LSB								1		
26	0		GO ₂ LINE PRESSURE (MONITOR 3) MSB LSB								GO ₂ LINE PRESSURE (MONITOR 3) MSB LSB								1		
27	0		CHAMBER PRESSURE (MONITOR 2) MSB LSB								CHAMBER PRESSURE (MONITOR 1) MSB LSB								1		
28	0			0		FUNCTION MONITOR C B A			POWER CONTROL FOR FIRING LOGIC C B A			CHAMBER PRESSURE (MONITOR 3) MSB LSB								1	
29	0		0	0	0	0	0	0	EMERGENCY SHUTOFF VALVES			LINE VALVES		VALVE COIL DRIVERS C B A			SPARK DRIVERS C B A		1		

TABLE II. APS/DIU STATUS REPORT COMMAND RESPONSES



the input redundancy by sequentially powering down sections and cycling through the assigned commands and verifying proper performance. The firing logics are also stimulated and the outputs monitored for proper operation while the drivers are inhibited and tested for shorts and/or opens. Similarly, the Strain Gauge Amplifiers and the Function Monitors are stimulated to verify their performance.

As the various tests are sequenced, the performance is stored in a series of two-bit codes to formulate a 16-bit word indicating the total test results. With proper performance on all circuits, the 16-bit word is all zeros. At the end of the test the status word is automatically loaded into the Status Monitor and shifted to the Data Terminal.

In appearance, the "self-test" command is issued to the APS/DIU. Several seconds pass and the next activity out of the unit is an automatic status word indicating the test results. The APS/DIU will not accept any commands during this test activity. And, regardless of its redundancy configuration prior to the self-test cycle, the system will automatically reset itself back into its prime mode of operation.

For example, if the unit has failed in its attempt to use Firing Logic "A" in the normal operating mode and has proceeded to use "B" continually, the system will be reset back to Firing Logic "A" following a "self-test" command. However, because "A" is, in fact, failed, switchover to "B" will occur as soon as the "A" set is tried. The unit will then continue to use "B" as it did prior to the self-test cycle.



3.3 MODULE DESIGNS

This section will detail and discuss the specific operation in each of the APS/DIU breadboard modules. The modules are oriented and constructed for versatility within the breadboard architecture and are not to be construed as a typical LSI chip design. Because of the high densities possible on an LSI chip, several of these schematics can be incorporated into one package.

The boards that are listed are identified by number both on the schematic and in the breadboard system itself. Some numbers do not appear and this is either because they have been designated to the Actuator Interface Digital Interface Unit or they have been eliminated due to a design change. Board No. 1, the Supervisory Command Comparator, has been eliminated from the original systems design.

The board coordinate system is a straightforward layout defined in Figure 1-A. Each board is capable of holding 24 sockets although only those required for a given circuit were used. All of the sockets used were 16 pin although in many cases only 14 pin devices were used. Where 14 pin devices were used, the pins 8 and 9 of the socket were not counted and the remaining 14 pins were counted for device correspondence, as shown in the illustration. These coordinates are labeled for each device on the schematics discussed in this section.

3.3.1 Supervisory Parity Checker; Board No. 2 (Figure 2)

This circuit is comprised of a parallel tree of exclusive OR's which monitors the 19 bits of information stored in the parallel storage registers. The parallel tree was constructed to minimize the propagation delay experienced between the time that the new information is entered and the validating state is set at the output. Valid parity enables the decoders (reference Figure 1).

There are two parity checkers per board with separate power inputs for each. However, both are operated from the same supply (A, B, C or D) and one checker monitors a one's register while the other monitors the corresponding zeros register.

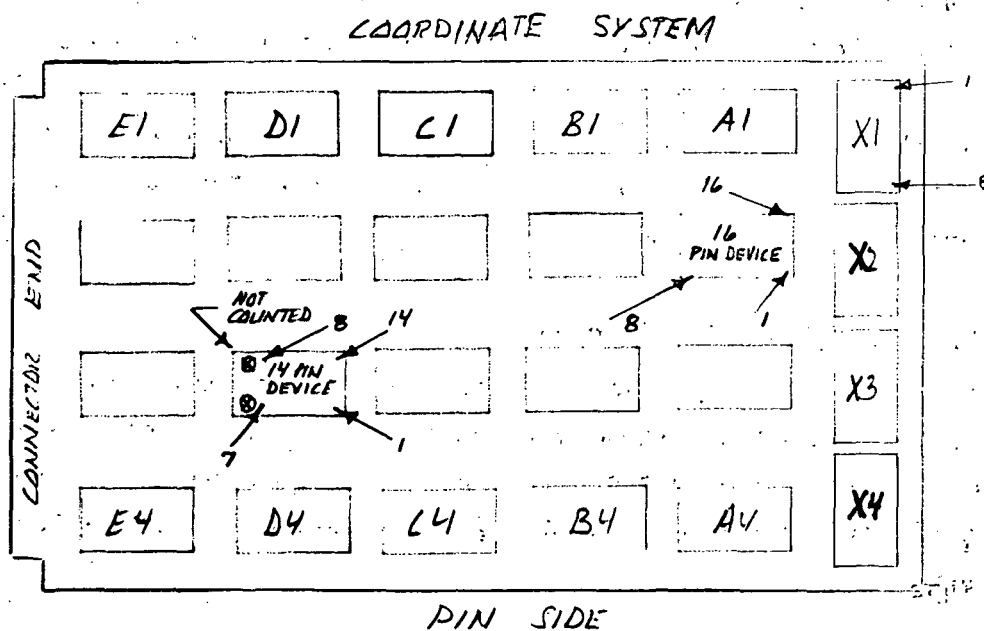
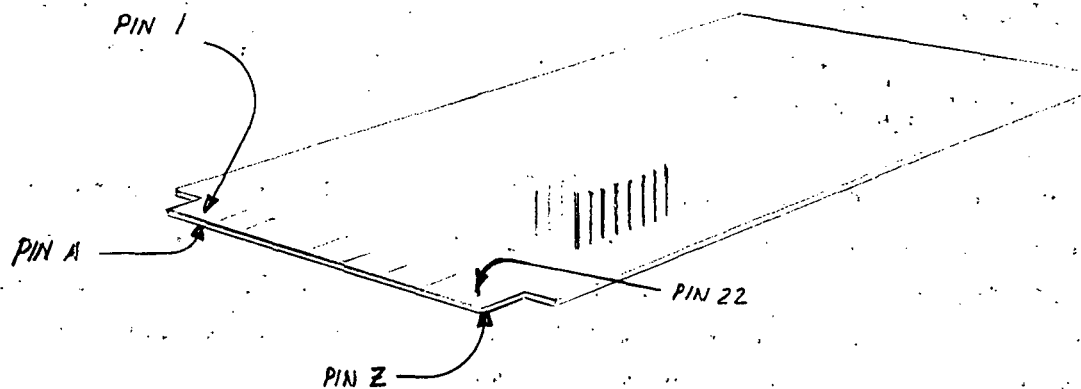
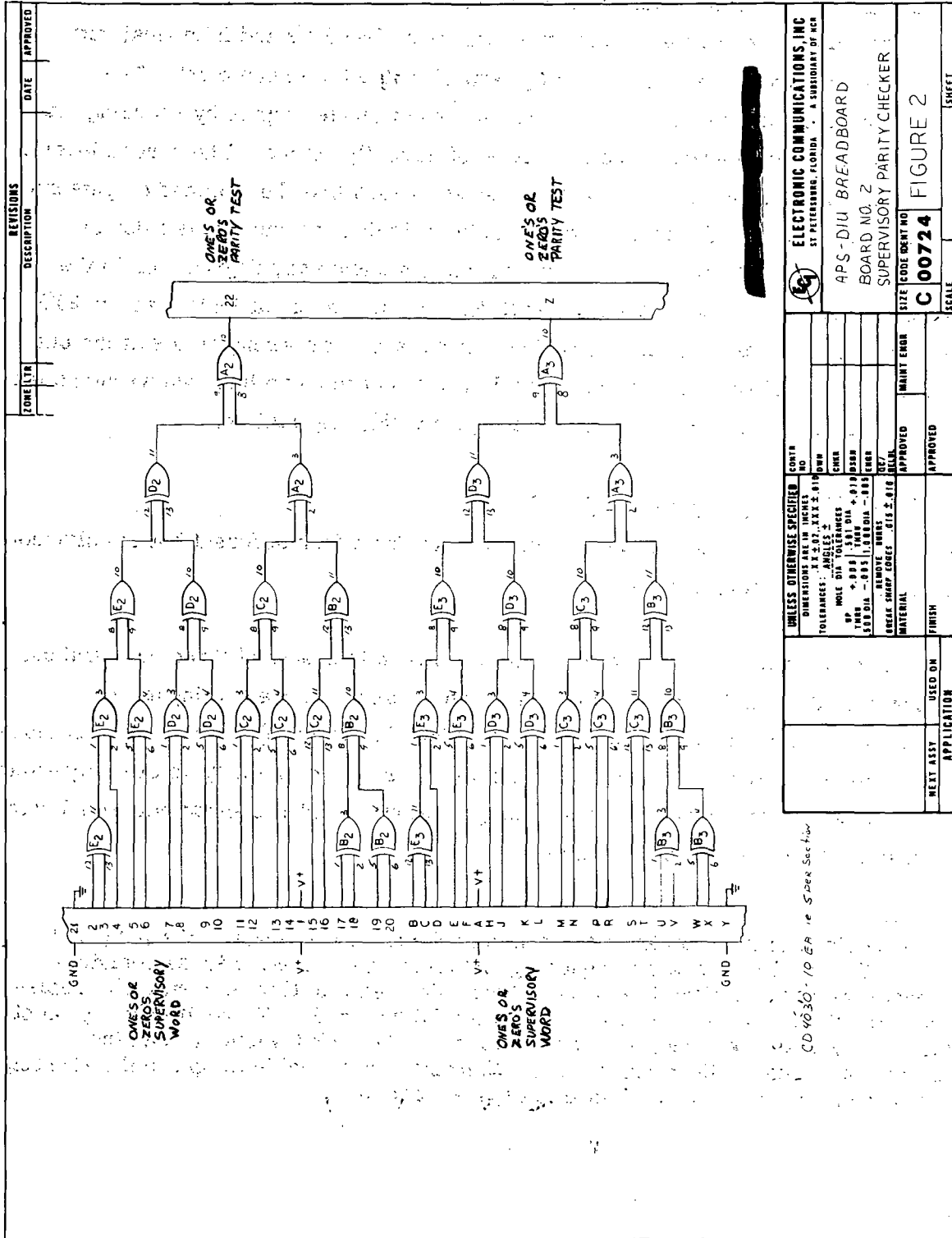


FIGURE 1-A. BOARD-COORDINATE SYSTEM



CD 4030 - 10 EA re S-Dev Section

FIGURE 2. PARITY CHECKER

ELECTRONIC COMMUNICATIONS, INC. ST. PETERSBURG, FLORIDA • A SUBSIDIARY OF RCA	
APS-DIU BREADBOARD BOARD NO. 2 SUPERVISORY PARITY CHECKER	
SIZE CODE ORIENT NO	FIGURE 2
C 00724	SCALE
NEET ASST	USED ON
APPLICATION	FINISH
APPROVED	MAINT ENGR
APPROVED	APPROVED



3.3.2 Single Bit Majority Voter; Board No. 3 (Figure 3)

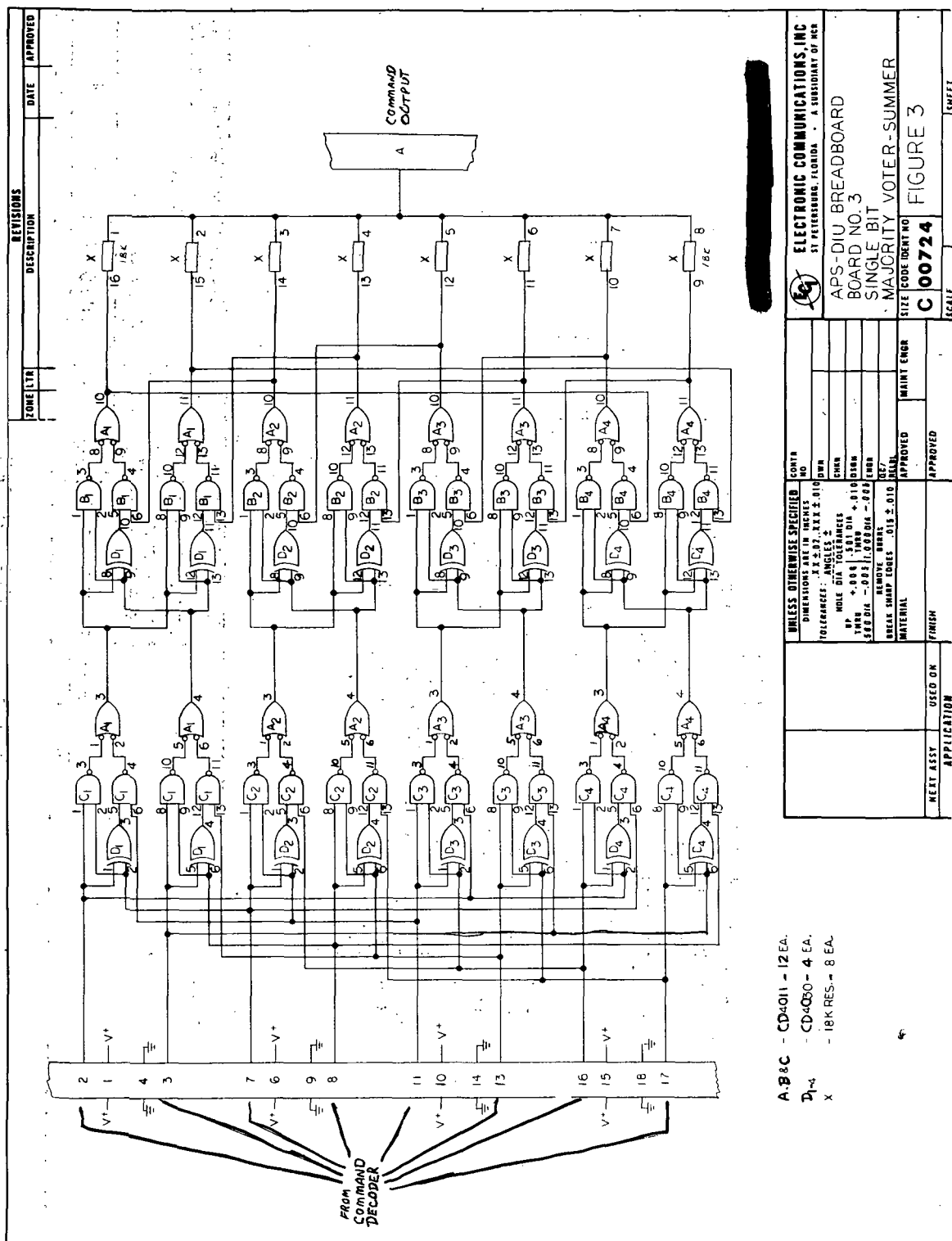
This circuit collects the command data from the eight decoders and inter-majority votes on two levels to a resistive summing network outputted to one point. The scheme is oriented to eliminate any two hard-failed or floated inputs by reducing this indication to a single line within the first level of majority voters. The second level of majority voters performs a bit-correction operation such that the summed outputs are all in the correct state. Above this, the module in itself is immune to two device failures. Open ⁽¹⁾ resistors at the output will not contribute any degradation to the signal state. Shorted output gates (two) will deteriorate the output logic level by 25% which leaves a 25% margin of additional level certainty. Two wrong states at the outputs of the first level of majority voters could not result in more than two wrong states at the summing resistor inputs resulting in, again a 25% degradation.

3.3.3 Serial Voter; Board No. 4 (Figure 4)

This circuit provides bit correction and correlation from four different but simultaneous serial inputs to four separate outputs.

A set of four majority voters views the input signals in four sets of three each and outputs corrected data against a single incorrect input each. Where two inputs to a majority voter are in some hard failure mode (high, low or open), there is no contribution to the RC summing network by that majority voter. Two majority voters may either fail or view two failed inputs and the summing network will still provide corrected data to the four recovery/driver output gates.

(1) Open resistors are considered the prime resistor failure mode in the APS/DIU designs. Within a final package employing LSI techniques, most of these resistors will necessarily be thin film deposit resistors. Shorted thin film or metal film resistor is about 0.01% of the probability of an open failure mode. To additionally protect against the short failure mode, series resistors may be added which increase the probability of an open failure mode. It is, therefore, reasonable to ignore the shorting failure mode because of its low impact on system reliability.



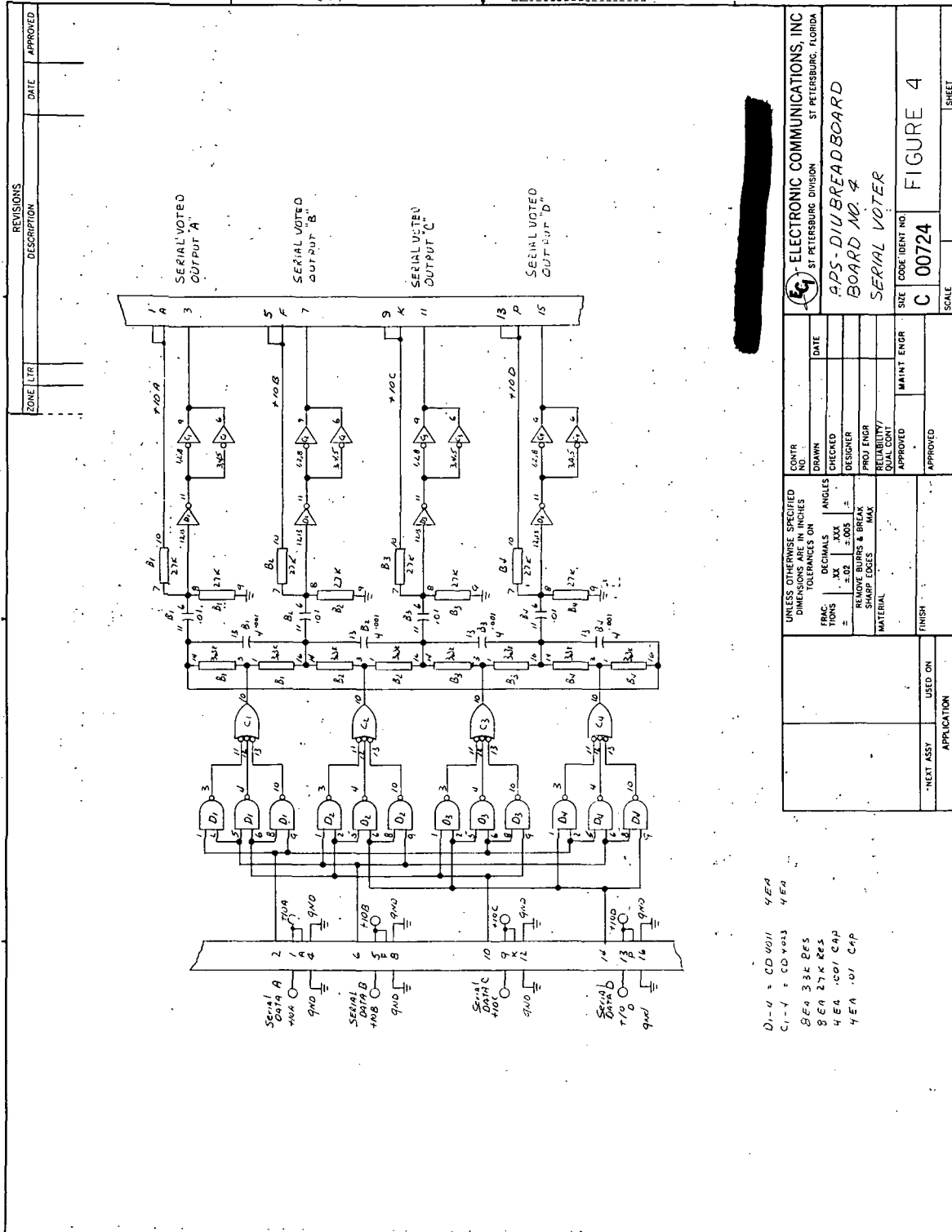


FIGURE 4. SERIAL VOTER



This circuit takes decided advantage of the 50% switching characteristics of CMOS logic devices. A bias network is added to the inputs of the recovery gates such that they may operate at lower input logic swings than normally required. The output gates are paralleled to provide additional drive to the lines within the breadboard.

The circuit will perform with no noted changes in the output if two of the input lines are shorted to ground, tied high, combined high and low or have different interfering signals of any frequencies. Two sets of different signals cause considerable confusion because the circuit cannot determine which two are correct.

3.3.4 Supervisory Serial and Storage Registers; Board Nos. 6 & 7 (Figure 5)

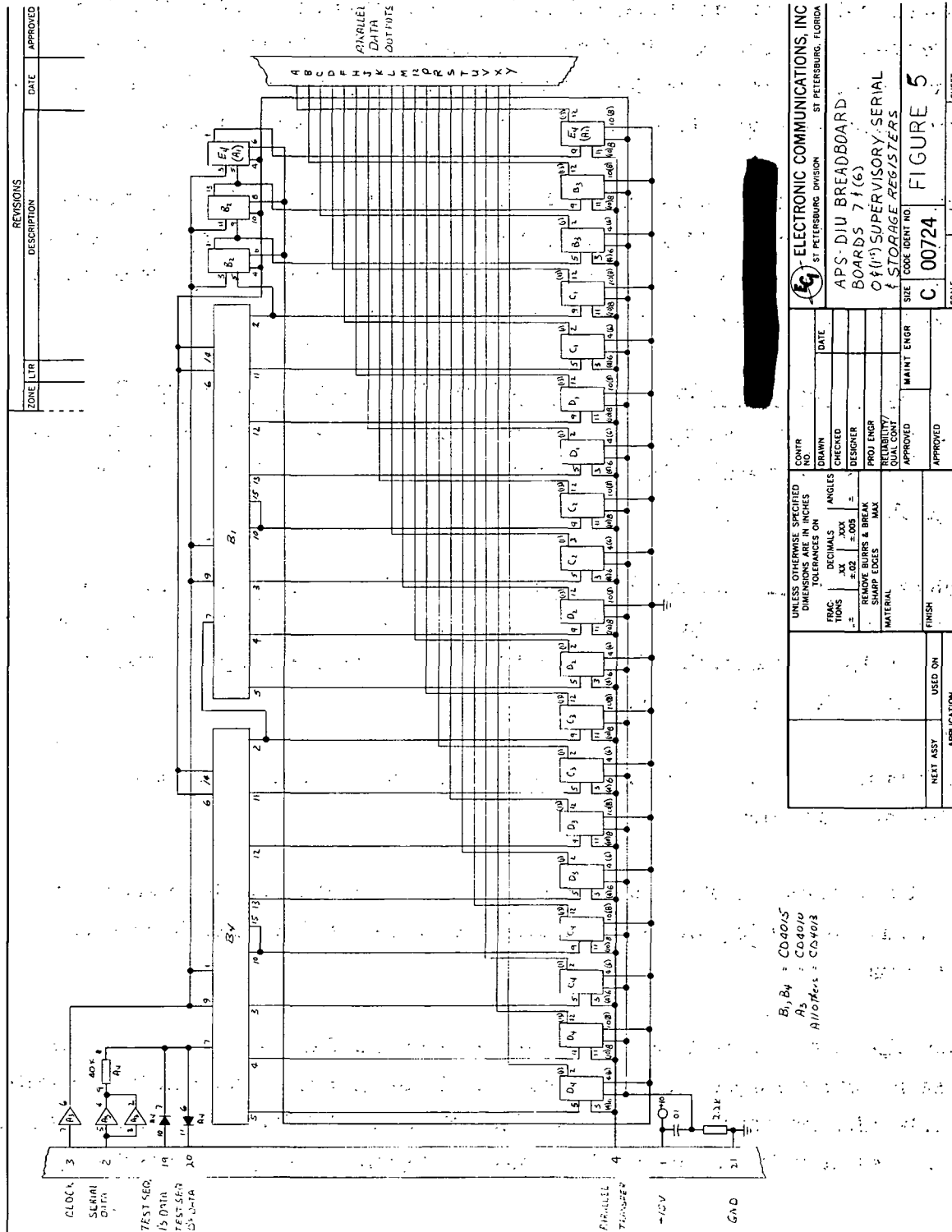
This schematic illustrates two types of similar boards, one for the 1's information and one for the 0's information. The difference is in the information taken off of the storage elements (Q of \bar{Q}).

The clock and data are buffered coming on to the board (not needed in LSI format) and they feed a 19 bit serial register. The "parallel transfer" input is, in fact, the "end-of-word" pulse detected within the System Clock Generator and this pulse loads the inputted data into the storage elements.

The information remains in storage for 20 microseconds while the next word (or "all-zero" pattern) is shifted in.

Of the 19 bits shown outputted, only 8 bits are employed in the APS/DIU breadboard. This added capability is provided in the event that there are changes to the system requirements.

The serial data input is buffered by two parallel buffers and feeds a 40 K resistor which is in series with the input to the shift register. At this junction, shown on the schematic, two diodes also input at this point labeled "Test Sequencer '1' Data" and "Test Sequencer '0' Data" respectively. Here, the Test Sequencer inputs the assigned words during



B₁, B₄ = C0401S
A₃ = C0401a
A₁₀, A₁₁ = C04013

ELECTRONIC COMMUNICATIONS, INC.		ST PETERSBURG DIVISION		ST PETERSBURG, FLORIDA	
APR-DIU BREADBOARD					
BOARDS 71(6)					
Q4(1) SUPERVISORY SERIAL					
STORAGE REGISTERS					
SIZE		CODE IDENT NO.		FIGURE 5	
C		00724			
SCALE		SHEET			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES		TOLERANCES ON		ANGLES	
FRACTIONS		DECIMALS		ANGLES	
XX		.XX		XXX	
±.02		±.005		±.005	
REMOVE BURRS & BREAK SHARP EDGES		MATERIAL		FINISH	
NEXT ASSY		USED ON		APPLICATION	
APPROVED		APPROVED		APPROVED	
MAINT ENGR		APPROVED		APPROVED	
QUAL CONT		APPROVED		APPROVED	
RELIABILITY		APPROVED		APPROVED	
PROJ ENGR		APPROVED		APPROVED	
DESIGNER		APPROVED		APPROVED	
CHECKED		APPROVED		APPROVED	
DRAWN		APPROVED		APPROVED	
DATE		APPROVED		APPROVED	



APS/DIU "self-test" and the diode configuration provides forced one's or forced zero's to override whatever information may be on the buffer at that given time. In the normal operating mode, these diodes are open.

3.3.5 One's Decoder; Board No. 8 (Figure 6)

This circuit has for its inputs, the eight encoded bits of the supervisory word that is loaded into the "ones" storage registers. There is a decoder for each of the four "ones" registers.

The decoding is straight forward binary-to-decimal decoding to output 1 of 29 possible commands as a 'zero' in a field of 'one's.

3.3.6 Zero's Decoder; Board No. 9 (Figure 7)

This board is identical to Board No. 8 except that it gets its inputs from the zero's registers.

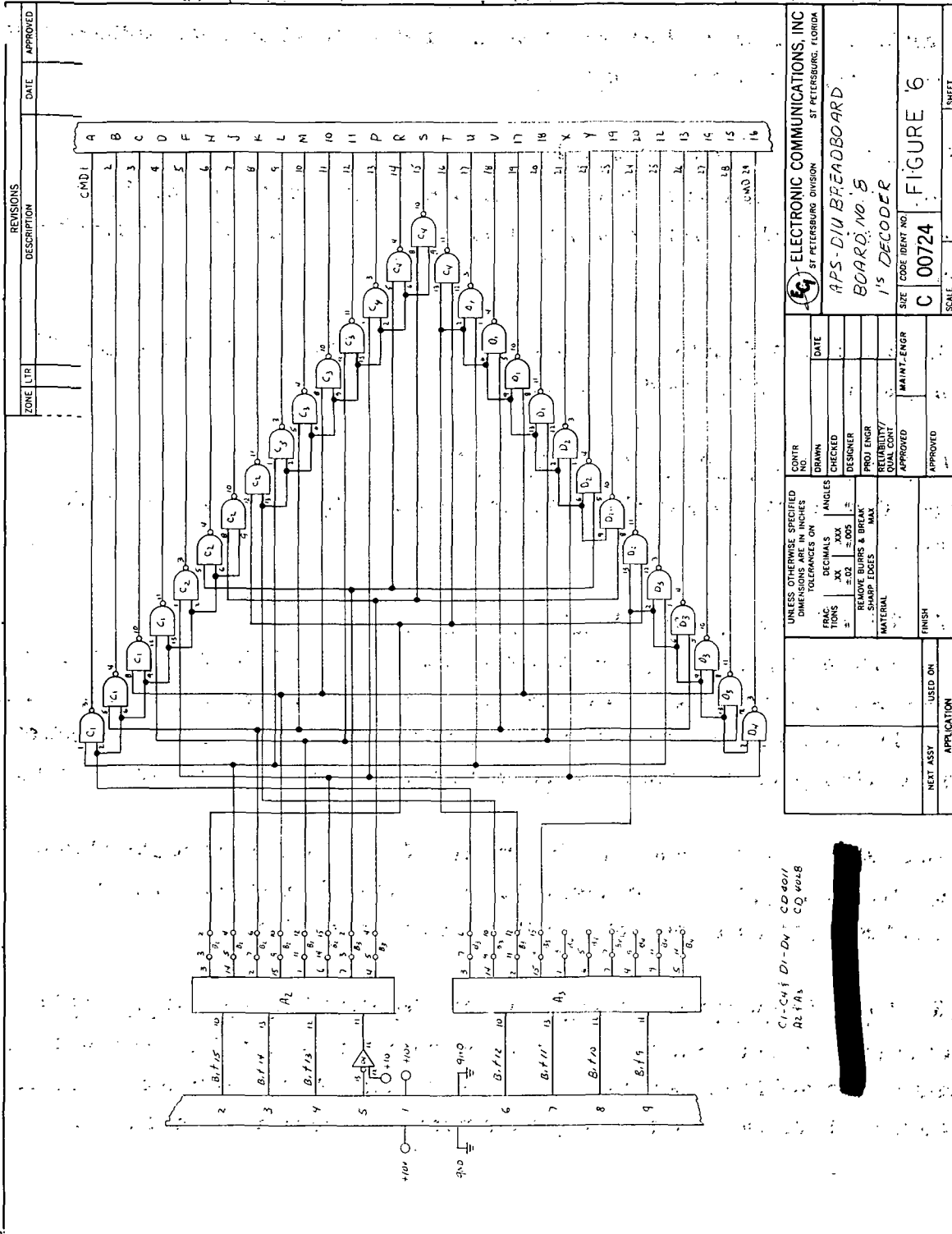
3.3.7 Status Monitor Multiplexer; Board No. 13 (Figure 8)

Sixteen of these boards are required to comprise the complete Status Monitor Multiplexer in four sets of four each. Each board has six 2-wide 4-bit multiplexers with appropriate control lines to steer one of the twelve 4-bit selected inputs to the output. The control lines are activated in accordance with the status word requested and by board location.

As can be seen by the diagram, straight forward AND-OR circuitry is employed with appropriate steering gates to the output. These circuits will present a unique problem in the LSI configuration because of the I/O pin limitation per chip.

3.3.8 Status Monitor Parity Generator and Shift Register; Board No. 14 (Figure 9)

This circuit receives the selected data from the multiplexer and the load and timed clock signals are inputted from the timing and control circuits. A parallel tree parity generator views the 16 bit input and the parity bit is loaded into the registers with the data.



C1-C4 & D1-D4 CD 4011
A2 & A3 CD 4048

ELECTRONIC COMMUNICATIONS, INC. ST PETERSBURG DIVISION ST PETERSBURG, FLORIDA	
APR 21 1968 BOARD NO. 5 1'S DECODER	
DATE	DATE
CONTR. NO.	DATE
DRAWN	CHECKED
DESIGNER	PROJ. ENGR.
RELIABILITY/	APPROVED
CONSTRUCTION	APPROVED
MATERIAL	APPROVED
FINISH	APPROVED
NEET ASSY	USED ON
APPLICATION	SCALE
C 00724	
FIGURE 6	
SHEET	

FIGURE 6. ONE'S DECODER

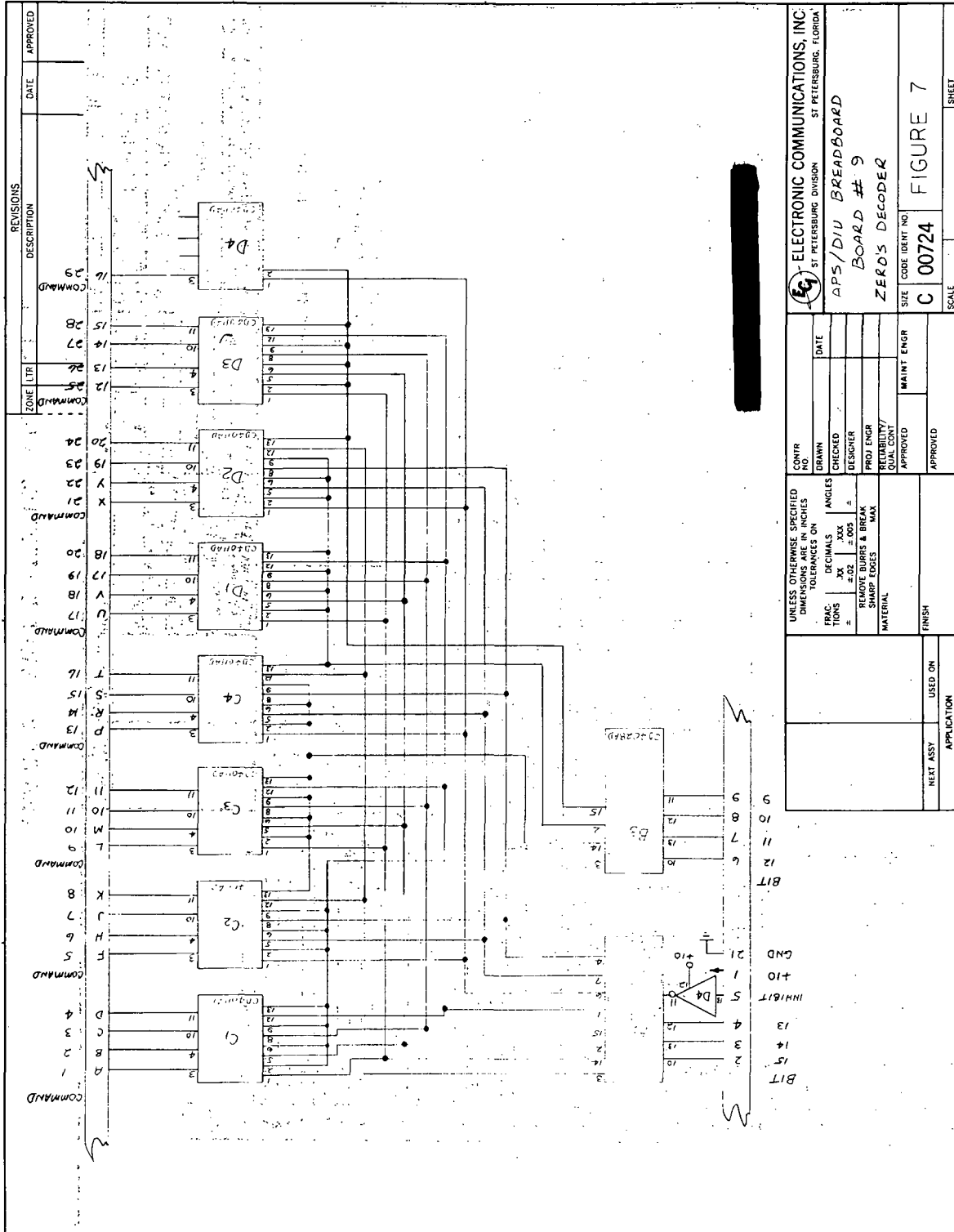
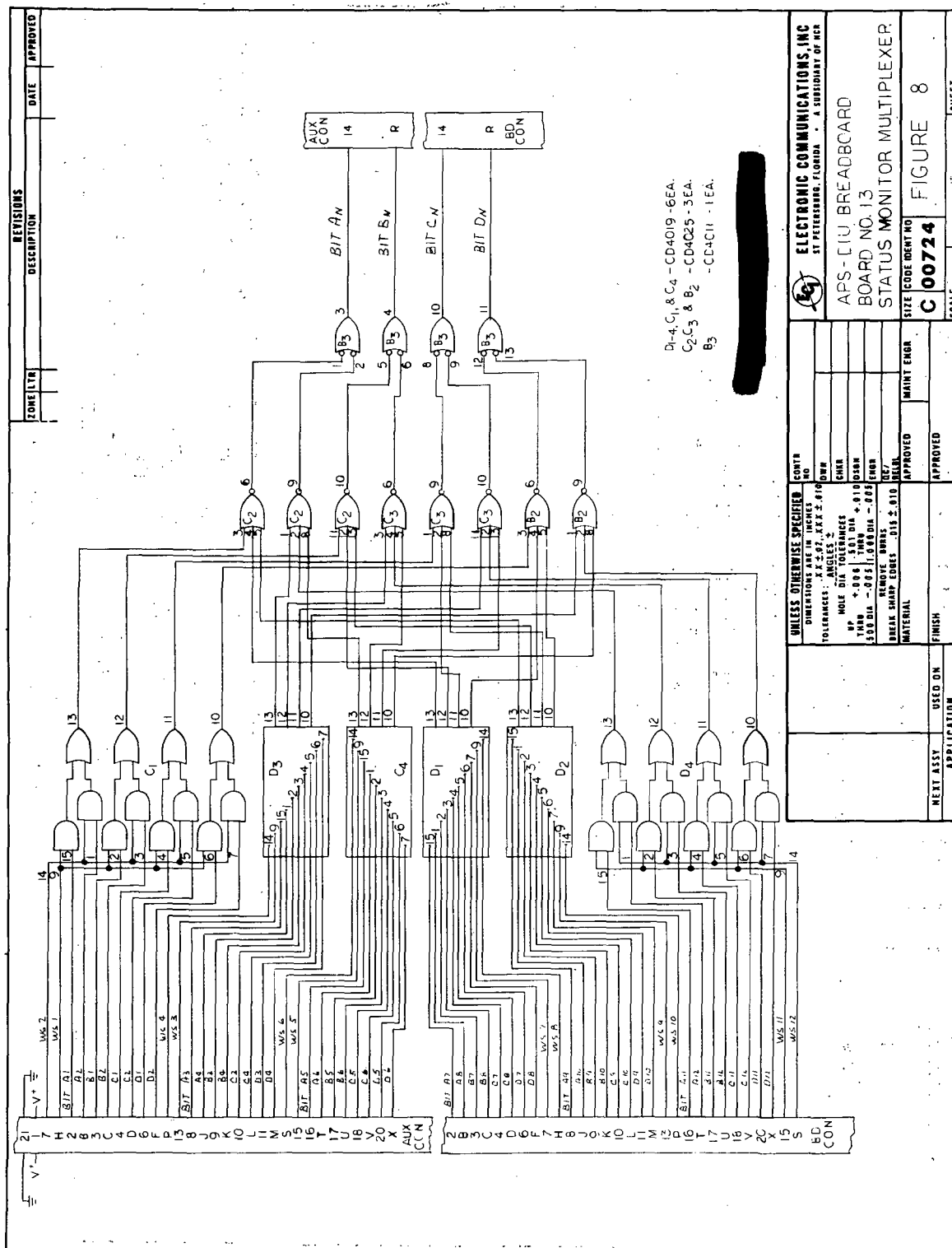


FIGURE 7. ZERO'S DECODER





Bit "one" is always preset to a "1" and bit "nineteen" is always preset to a "0". The remaining 17 bits are data plus parity.

There are two shift registers with parity generators per board and two boards required for the APS/DIU.

3.3.9 Polar RZ Modulator; Board No. 16 (Figure 10)

To drive the shielded twisted-pair lines to the Data Terminal from the APS/DIU with Polar RZ data, a core memory driver (S/N 55325) from Texas Instruments, was selected to perform as a line driver. Here, the polar RZ waveform can be achieved directly utilizing the internal logic configuration with data and clock as inputs. The device has 600 ma driving capability which is more than sufficient to drive the 75 ohm line impedance.

The input buffers perform a CMOS-to-TTL conversion for both the data and clock and these feed the polar RZ drivers. Each polar RZ driver has a transistor configuration on its output such that in the "one" state, one side of the line is tied to +5 while the other is tied to ground. In the "zero" state, the opposite line is tied to +5 while its alternate is grounded. During the "no-data" state, both output lines are open. The waveforms are shown on the schematic.

3.3.10 Line Receiver-Photo Isolator Interface Circuit; Board No. 18 (Figure 11)

This circuit provides the isolation and data recovery from each line that inputs to the ISVC circuits. The primary of the board is powered separately from the remainder of the APS/DIU. Two comparators sense the "ones" and "zero's" separately and drive photo-isolator diodes. The network on the output of the photo-diodes provides both gain and high speed recovery of the bit waveshapes. The diode network along with the biasing configuration at the input of the output comparator, provides temperature compensation for the temperature characteristics of the photo-diode.



The photo-isolating concept utilized in this circuit is not a new or difficult circuit to design. However, making a photo-isolator perform consistently throughout the temperature of -55°C to $+125^{\circ}\text{C}$ is difficult because of the photo-diode characteristics at $+125^{\circ}\text{C}$. As a result, this circuit became more complex than is "reasonable" for its function. An industry search reveals that other materials (different from the gallium arsenide used in the MCD-4) were being investigated for application in photo-isolation and devices should be available during the last quarter of 1972. The circuit developed for the APS/DIU proves the feasibility of this technique; better devices would certainly reduce the functional complexity.

3.3.11 System Clock Generator; Board No. 19 (Figure 12)

The function of this circuit is to extract the clock information from the data that is inputted to the APS/DIU. Since there is an all "zero" input when no data is present, the clock will be continuous. The data coming out of both sides of the Line Receivers is either a "one" or "zero" and these are Ored at the input to each clock generator in direct correspondence A, B, C, and D.

The leading edges are detected at the output of the Or circuit by a logic differentiator which is capacitively timed to yield a 250 nanosecond pulse per each data bit. These clock pulses are buffered and outputted off the board. They also feed a "missing-pulse" detector circuit comprised of a driver, diode and RC circuit. Here, the 20th bit slot is identified and this pulse is shaped by another logic differentiator timed to 500 nanoseconds and labeled "End-of-Word" pulse.

3.3.12 (Dual) Tracking Analog-to-Digital Converter; Board No. 20 (Figure 13)

There are two A/D converters per board as detailed in the schematic. The schematic lists the dual coordinates for the components required.

The A/D converter is oriented to convert a ± 5 volt analog input to an 8-bit digital number in two's complement form. The converter will track the input by counting either up or down depending on the relative polarity of the input to the feedback amplifier. This

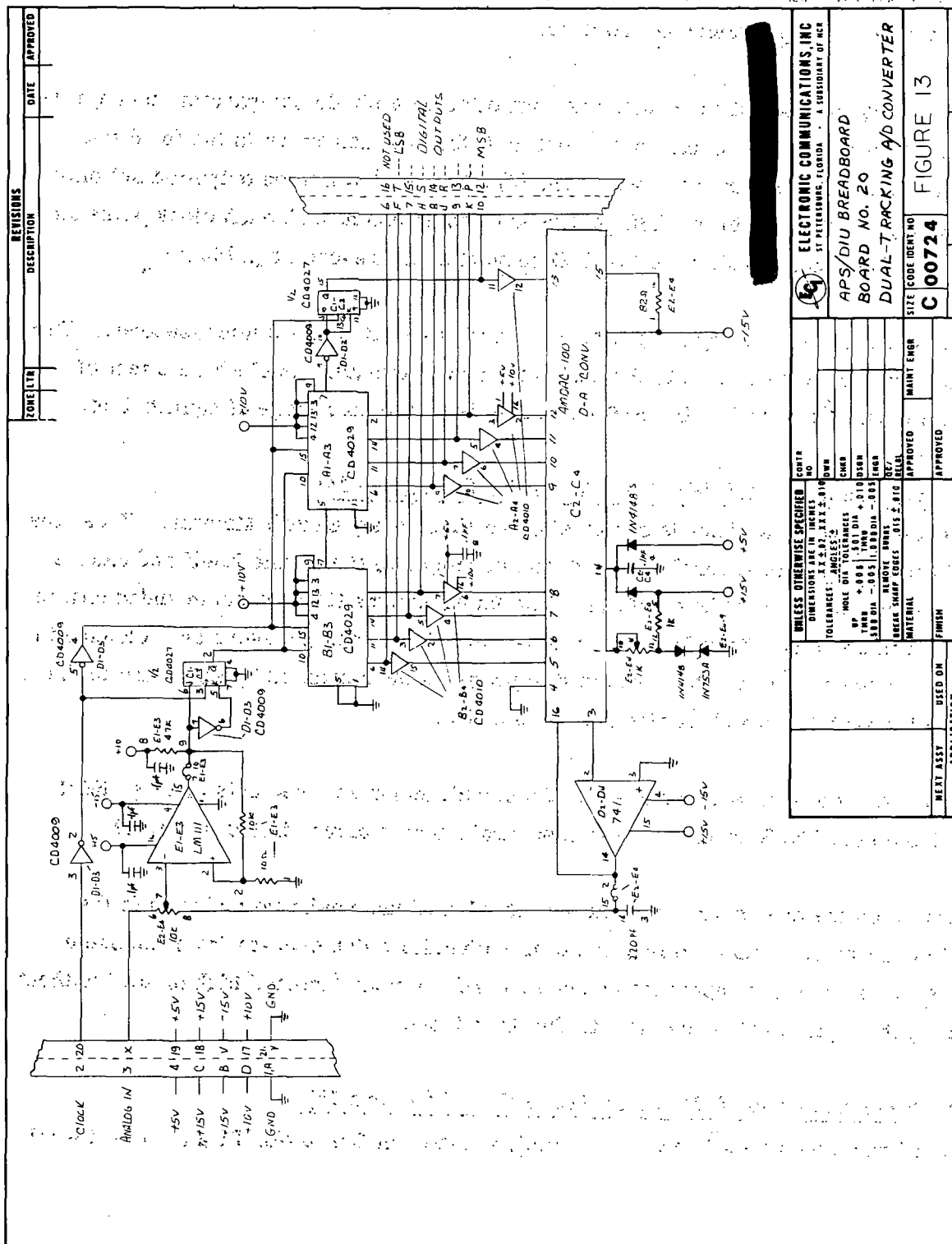


FIGURE 13. DUAL-TRACKING A/D CONVERTER



allows the information to be accessed at any time except during the actual clock period which is approximately 2 microsecond wide.

The up/down count mode of the counter is controlled by a single comparator in conjunction with a flip-flop. The counter will count until the D/A converter in the feedback loop equals the amplitude of the input. Nine (9) bits are shown to be outputted but only 8 are employed. The 9th bit or LSB continues to complement with each clock pulse as does the up/down count mode once the A/D converter has reached equilibrium.

The input clock is 12.5 Kc with a clock pulse width approximately 2 microseconds. This permits maximum access time to the converter and eliminates the clocking effect of comparator oscillations when the A/D converter is on the near-edge of equilibrium.

3.3.13 Emergency Shutoff Monitor; Board No. 21 (Figure 14)

This circuit is one of two boards comprising the Emergency Shutoff Monitor. Here, the logic, in triplex, seeks several faults which are unique to the engine itself and causes closure of the Emergency Shutoff Valve. The faults include (1) an uncommanded engine burn which is detected either by sensing unwarranted chamber pressure or a closure in the engine-valve switches; (2) a drop in line pressure accompanied by a closure in the engine-valve switches which is also not commanded.

These conditions are sensed and ORed at the circuit output in three sets of three NOR gates. Each set of NOR gates will feed a separate series driver in Board No. 22.

As is shown on the schematic, the inputs to this board use resistive isolation to the inputs to each gate. This is to isolate similar circuits which operate from the same source such that any two inputs may assume a failure mode (shorted high or low) without disturbing the logic level of the input to the third input.

3.3.14 Emergency Shutoff Monitor; Board No. 22 (Figure 15)

This board receives as its inputs, the decisions made on Board No. 21 and the external

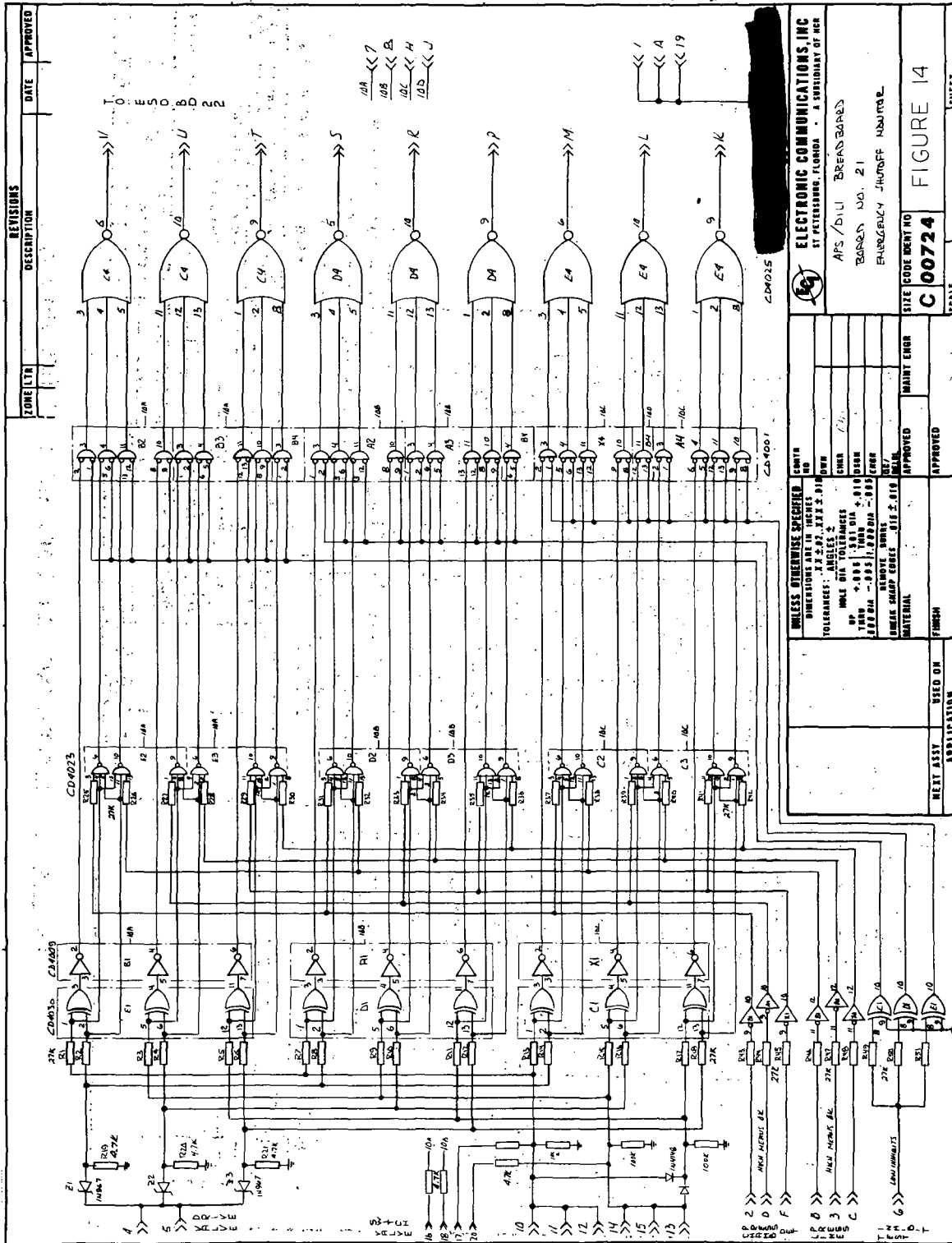
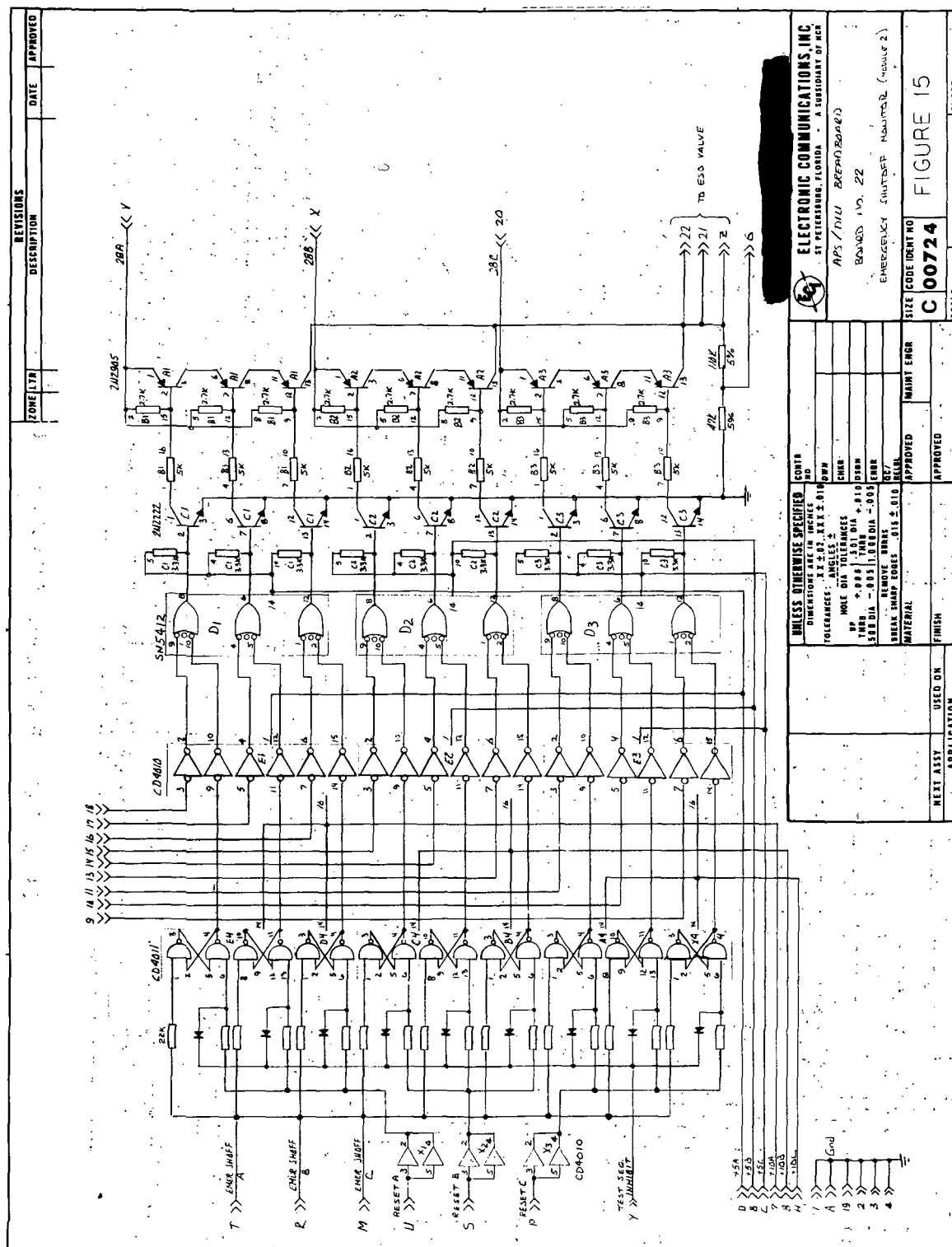


FIGURE 14. EMERGENCY SHUTOFF MONITOR





command for emergency shutoff. Again, the logic and drivers are configured in triplex/parallel to provide dual failure immunity.

The emergency shutoff and reset commands from the "Input Data Validity Comparison" circuitry feed a triplex set of three latches. The latches feed a set of CD 4010's which are used for CMOS-to-TTL conversion for both the external commands and the information fed in from Board No. 21. These data are ORed in TTL 5412's which are open-collector gates used to control the drivers. Each driver set is comprised of three NPN transistors gated on essentially in parallel (but by different sources) which drive a set of PNP transistors in series. Here, all three inputs must be identical to turn the driver "on" which protects a driver set against two shorted transistors. As shown, there are three driver sets in parallel which protect against two open-failed transistors.

During "Self-Test" the Emergency Shutoff Monitor is inhibited both on Board No. 21 and Board No. 22. On Board No 22, it is inhibited at the latches such that ESO does not get activated during the input circuit tests.

3.3.15 Power Enable/Disable Module; Types "A", "B" and "C"

Board No. 23 (Figures 16, 17 and 18)

The function of these circuits is to provide power to the Firing Logic boards selectively such that they operate in a sequence according to failure. The sequence will always be "A"-to-"B"-to-"C"-to-"off."

The Power Enable/Disable circuits will be discussed in order of sequence. Although all three do perform the same basic function, there are fundamental differences based on the sequencing requirements.

3.3.15.1 Board Type "A"

The input commands as shown on Figure 16, perform the following functions:

- (1) "Inhibit Function Monitor Control"- This is a Test Sequencer input which is active only during certain portions of the self-test activity

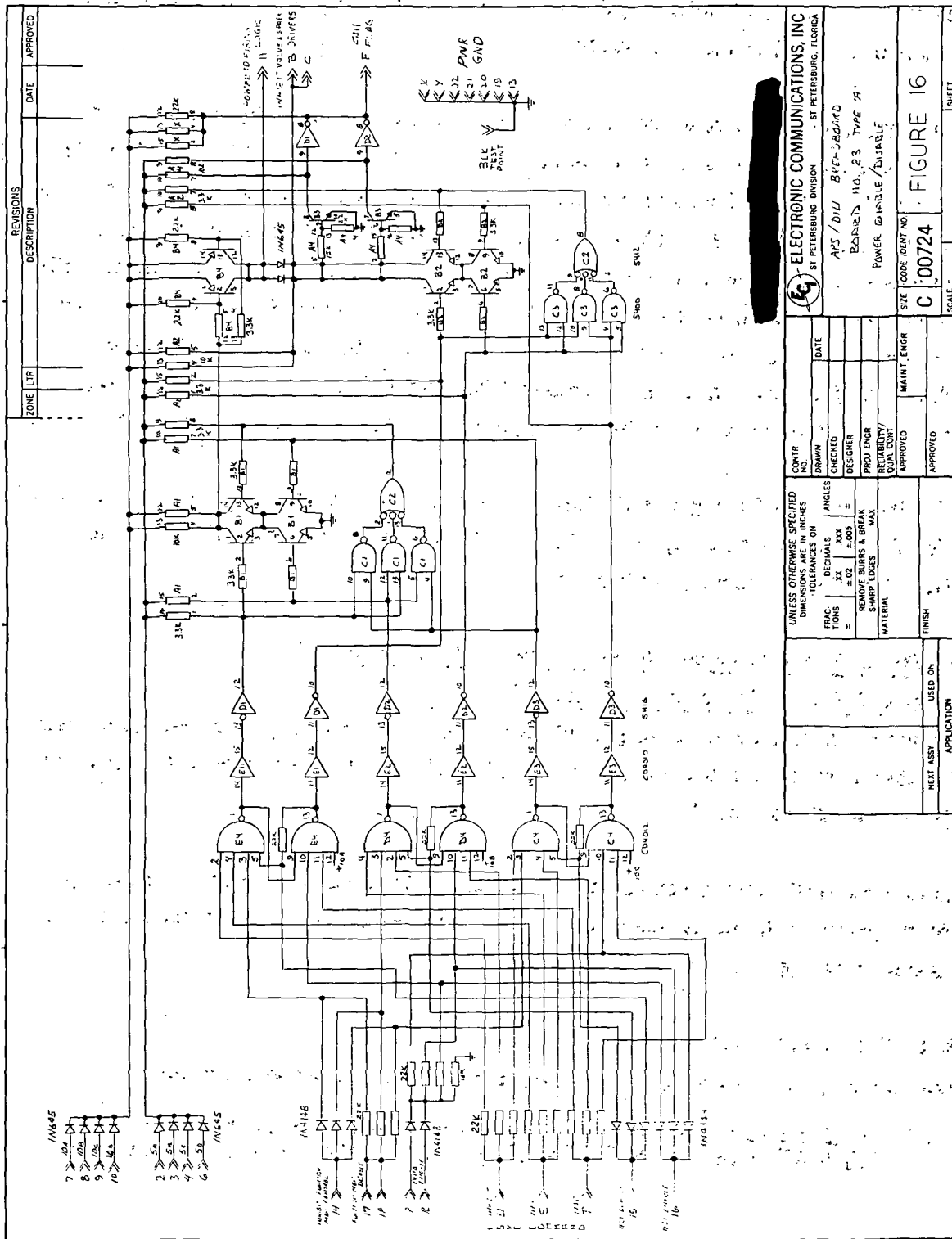


FIGURE 16. TYPE "A" POWER ENABLE/DISABLE

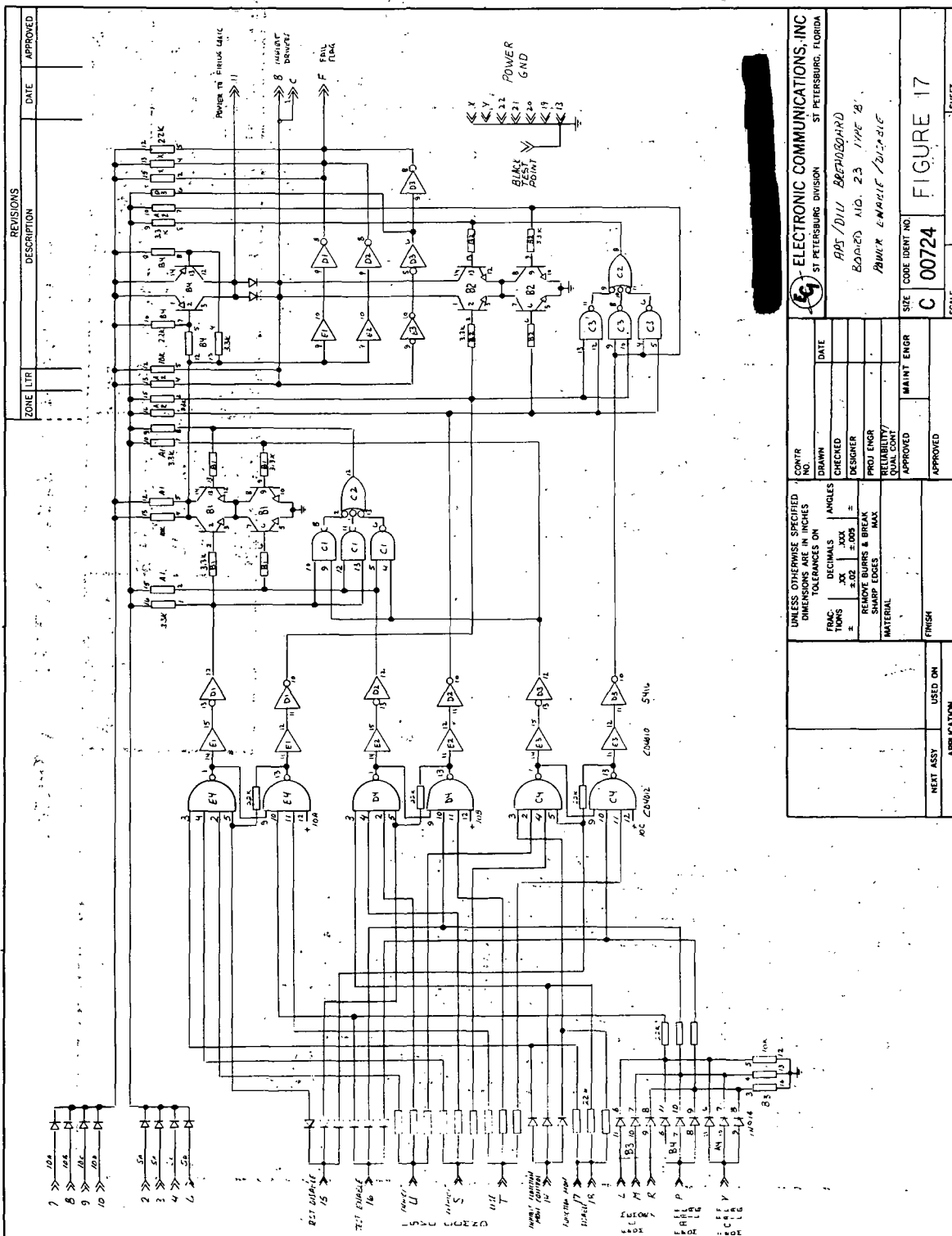


FIGURE 17. TYPE "B" POWER ENABLE/DISABLE

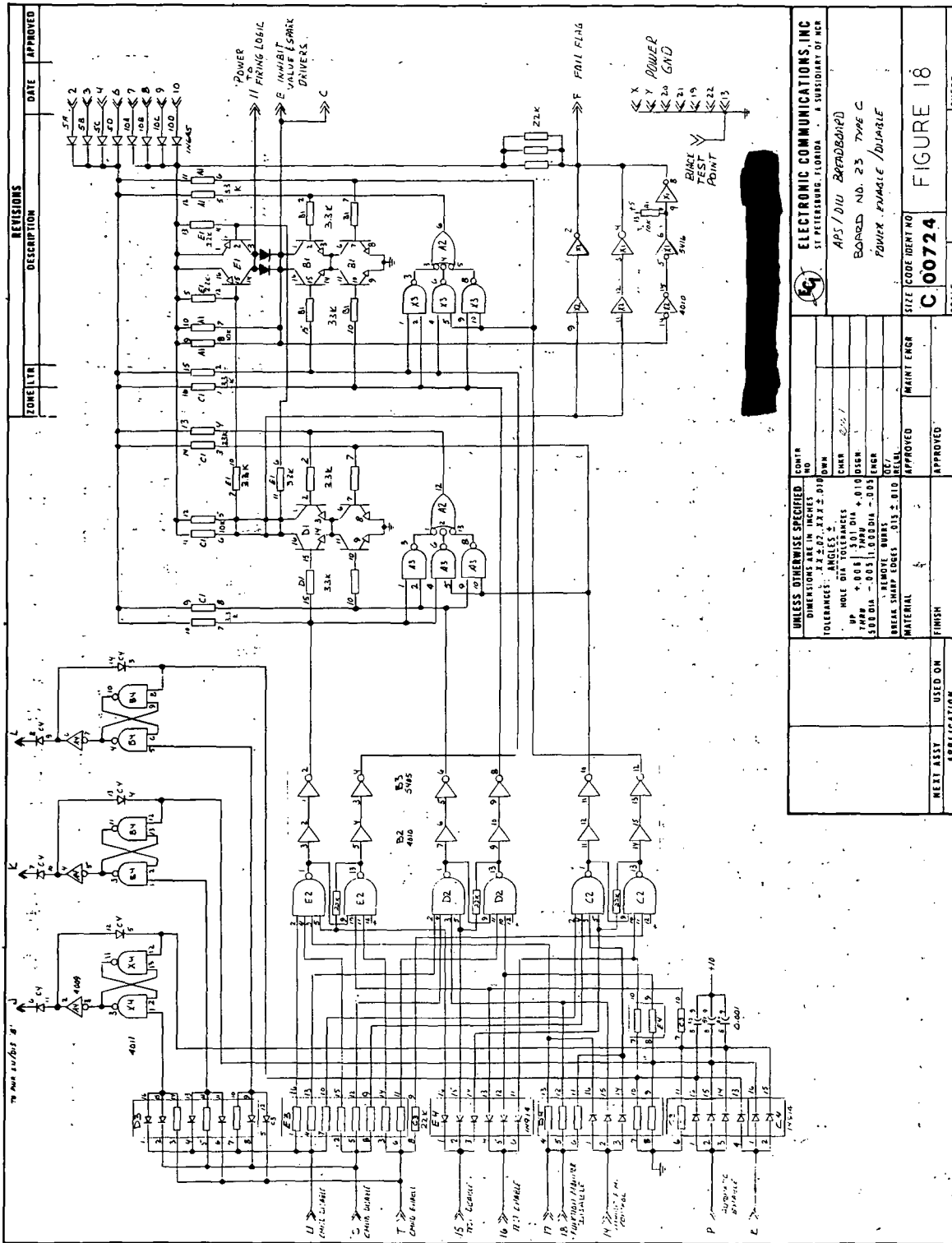


FIGURE 18. TYPE "C" POWER ENABLE/DISABLE



to inhibit the associated Function Monitor from shutting down the power to "A" Firing Logic. As can be seen from the logic configuration, a low at the Function Monitor Disable input would set the latches E4, D4 and C4 to an "off" state. This low is forced high by the inhibit input during Test Sequencer activity so that the latch state is not altered.

(2) "Function Monitor Disable" - This signal comes from the Function Monitor as an indication that Firing Logic "A" is not operating correctly. A low at this input sets the latches to an "off" state as discussed above.

(3) "Auto Enable" - If this point were brought low, the latches would set to an "on" state. However, because the idea of a "try-again" scheme was dropped in the design of the DIU, this input is tied high and not used in this module.

(4) "ISVC Command; Inhibit, Inhibit and Use" - These inputs are the redundancy override commands coming from the ISVC circuits. The "use" input sets the latches to the "on" state and corresponds to the "use Firing Logic 'A'" command. The two inhibit inputs set the latches to the "off" state and are, in fact, the "use Firing Logic 'B'" and "use Firing Logic 'C'" commands. Here, when a Firing Logic set different from "A" is programmed on, the inhibit command insures that "A" is off.

(5) "Test Enable" and "Test Disable" - These inputs are Test Sequencer inputs and are only active during certain portion of the self-test.

The logic within the Power Enable/Disable function is a majority voted set driving quad-transistor sets to either power or ground the Firing Logic power lines. The design intent of the board is to yield single failure immunity in being able to turn power on to the Firing Logic and to be dual-failure immune in being able to issue a "fail-flag" to turn on the next backup.

This board, as well as types "B" and "C" should be implemented differently which has been proven by this system breadboard study. This is discussed within the "Conclusions and Recommendations" portion of this final report.



3.3.15.2 Board Type "B"

The input commands to this board perform an identical function as listed for Board "A" with the following exceptions:

- a. Pin P receives its input from Power Enable/Disable Board Type "A" which goes low if Board "A" was disabled automatically.
- b. Board "B" will turn-on ONLY if Board "C" has not been previously tried automatically and it is not presently on as indicated by the inputs on pins L, M, R, and V.

Table III is a truth table indicating the states and the sequence of operation applicable to all three boards.

Any board may be turned on manually regardless of the system state. "B" will turn on automatically only if "A" failed and only if "C" is not on or has not been turned on automatically, because of a previous failure in "B".

The diode configuration shown for the "A" Fail Flag, "C" Fail Flag and "C" Memory permits these conditions of operation. If either the "C" Memory or the "C" Fail Flag are high, "B" cannot be turned on when "A" Fail Flag goes low.

The Fail Flag mechanism for board "B" is derived from two sources and hardware ORed at the output. One source which drives parallel gates is the quad transistor voter located at B1; if this fails open, the Fail Flag will go low. The other source is the Firing Logic power output which, when it goes low, a single gate string brings the Fail Flag low.

3.3.15.3 Board Type "C"

The input commands to this board function identically as those described for Board Type "A" with exception to the "Automatic Enable" which inputs on pins P and R. Here, both inputs must be low in order for the latches to be set to the "on" state. These inputs come from the "A" and "B" Fail Flags and "C" will turn on until both have failed low. When this occurs, the three latches X4, B4 and B4 shown at the top of the schematic "memorize" that an automatic enable has been exercised. This insures that, in the



STATES	"A" FAIL FLAG	"B" FAIL FLAG	"C" FAIL FLAG	"C" MEMORY
MANUAL				
A commanded "on" B off; C off	1	0	0	0
B commanded "on" A off; C off	0	1	0	0
C commanded "on" A off; B off	0	0	1	0
AUTOMATIC				
A on; B off; C off	1	0	0	0
A fail; B on; C off	0	1	0	0
A fail; B fail; C on	0	0	1	1
C fail; B fail; C fail	0	0	0	1

**TABLE III. POWER ENABLE/DISABLE FAILURE
SEQUENCE AND MANUAL CONTROL**

event of "C" failing, "B" will not be turned back on. When these latches have been set, their state is also diode ORed, into the enable junction such that the enable latches are not held in a forced mode. This will permit the "C" Function Monitor to cause a disable in the event of a "C" Firing Logic failure.

The "memory" latches will be reset if any manual command is issued whether it be to turn on "A", "B" or "C". Once a manual command is issued, the system then returns to its automatic sequencing mode as a function of failure.



3.3.16 Function Monitor; Board No. 24 (Figure 19)

This circuit monitors the Firing Logic valve and spark pulses, the Valve Switch closures and the Chamber Pressure and determines if the system is performing normally within the given logic set. There is an accompanying Function Monitor for each of the Firing Logic sets.

As shown at the input, the comparisons of the above information is made in Exclusive OR gates. The resultant states are ORed in C1, C2 and C3 simultaneously. Here, a one-shot is triggered and ANDed with the one-shot input signal after it has passed through some delay gates.

The purpose of the one-shot is to create an inhibit-time to block out sensing the difference between the valve and spark pulses and the difference between when the ignition is commanded and actual chamber pressure is detected. The test is, then, a kind of "reasonableness" test to verify that the system is performing approximately as expected. The one-shot inhibit time is approximately 15 milliseconds.

If a failure were to occur, it would be detected within 15 milliseconds of turn-on command and the majority voting quad-transistors would output a "low" to the Power Enable/Disable logic to disable that Firing Logic set.

Two failures that would majority-vote to cause a disable signal would eliminate that Firing Logic set and turn on the next backup. Two failures that would cause failure to indicate a disable signal leaves the system either normal or vulnerable to a third failure occurring somewhere in the Firing Logic. Manual control would then be required to switch over to a working backup logic set.

3.3.17 Firing Logic; Board No. 25 (Figure 20)

This circuit executes the "turn-on" and "turn-off" commands outputted by the ISVC circuits. Upon receipt of the "turn-on" command, the logic starts the ignition pulse, waits 10 milliseconds and begins the valve pulse, holds both pulses on until it receives

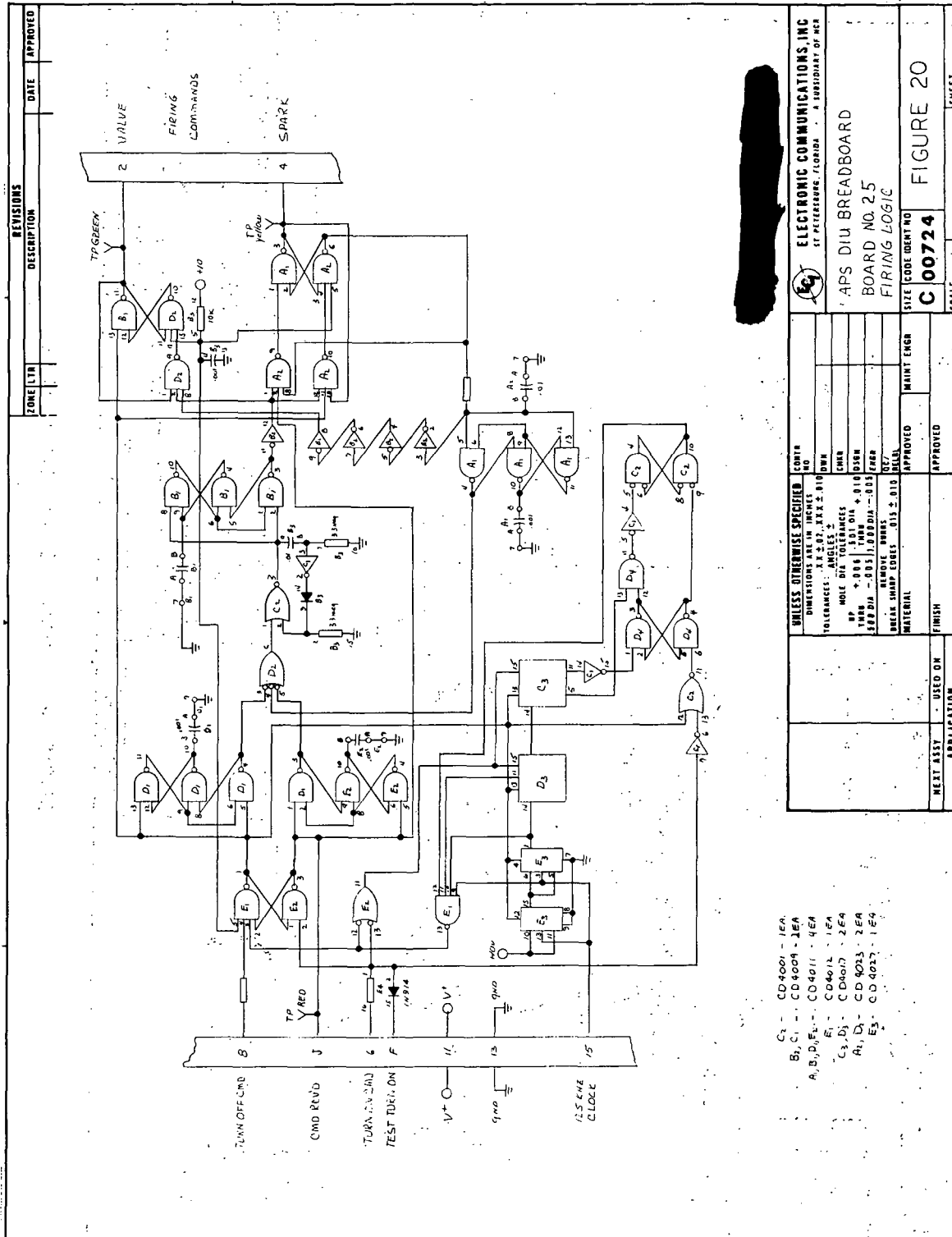


FIGURE 20. FIRING LOGIC



a "turn-off" command or clocks out 50 milliseconds; whichever comes first.

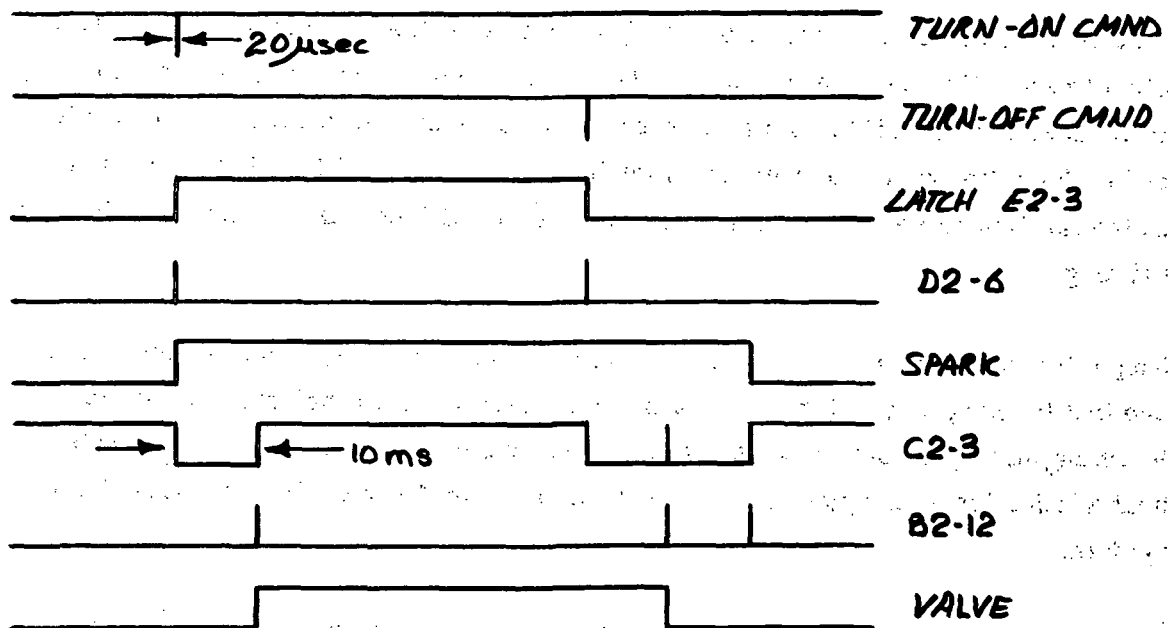
If a "turn-off" command occurs first, the logic turns off the valve 10 milliseconds after receipt of turn-off to compensate for the delayed turn-on. Then, in an additional 10 milliseconds, it turns off the ignition pulse. If it is permitted to time-out to 50 milliseconds, the valve pulse will remain on for 50 milliseconds and then it is turned off while the ignition pulse stays on for an additional 10 milliseconds. Figure 21 illustrates this timing.

Although this relative valve and spark timing is subject to change, the thinking was to insure that burning would start by initiating the spark prior to the entry of fuel and maintaining that spark until after the valves were closed, insuring complete burning without wetting the spark points. This insures that each burn cycle is initiated with dry points.

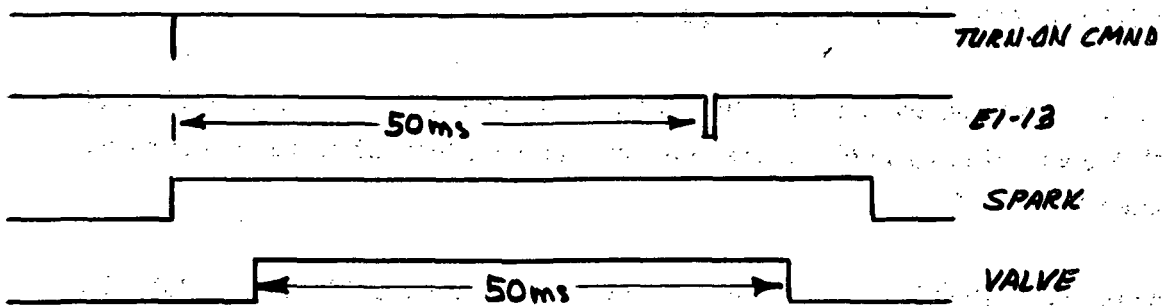
Functionally, the process begins with the 20 microseconds "on" command being received on pin 6. This sets latch E1/E2 which also sets latch B1/D2 to turn on the "spark" pulse. The change-in-state of latch E1/E2 is detected by the logic differentiator D1/E2/E2 to trigger the one-shot (10 ms) C2/C1. The end of the one-shot period is detected by the logic differentiator B1/B1/B1 which creates a pulse that is Nanded in gate A2(9). This sets latch A1/A2 to begin the valve pulse.

Now, the valve and spark pulses continue until a turn-off command is received at the latch E1/E2 either by ISVC command or by automatic turn-off as timed out by the counter E3/D3/C3.

Once the latch E1/E2 is reset, the logic differentiator D1/D1/D1 senses this change and re-triggers the one-shot. The logic differentiator B1/B1/B1 recognizes the end of the one-shot period and resets the valve pulse latch A1/A2. This delays the turn-off of the valve the same amount of time that it was delayed in turn-on. The logic differentiator A1/A1/A1 recognizes that the valve pulse latch was reset and it steers another trigger



COMMANDED TURN-ON & TURN-OFF



COMMANDED TURN-ON & AUTOMATIC TURN-OFF

FIGURE 21. FIRING LOGIC TIMING



pulse back to the one-shot. Again, a one-shot pulse is generated and detected by B1/B1/B1. The last differentiator pulse then resets the spark latch B1/D2. The string of inverters B2 delays the change-in-state of the valve pulse latch from reaching gate D2 until after the one-shot pulse has been restarted.

In review, the one-shot C2/C1 is used to generate three time delays for each engine firing; the first to delay the valve-on T amount after spark has been turned on; the second to delay valve-off T amount to maintain proper valve duration; and the third to turn-off the spark T amount after the valve has been turned off.

To keep the engine "on" full time, a command must be received more frequently than 50 ms to inhibit the automatic turn-off.

3.3.18 Chamber Pressure Amplifier/Comparator and A/D Converter; Board No. 26, (Figure 22)

This circuit monitors the Chamber Pressure Transducer with an internal strain gauge assumed to have a nominal resistance of 511 ohms. The amplifiers are presently scaled to output 1 volt per 10 ohm change in the strain gauge.

Both the type of transducer and the amplifier scaling as assumed to be subject to change. Therefore, the breadboard was fabricated with plug-in flexibility such that the configuration and/or scaling is easily altered.

In the circuit, three amplifiers monitor a single bridge and feed three comparators. The amplifiers are scaled for approximately 1 volt/10 ohm change in the bridge and the threshold comparators will switch at approximately a 1 volt change in the amplifiers.

The linear outputs of the amplifiers is digitized by A/D Converters (previously discussed) one of which is fabricated on this board and monitors Chamber Pressure Amplifier "A". The A/D information is for status monitoring information. The threshold comparators perform a "reasonableness" test to verify the presence of a chamber burn and this information is used in the Function Monitors and the Emergency Shutoff Monitor as discussed before.



In a LSI version of an APS/DIU, this circuit would be fabricated using microelectronic technology with chip-and-wire bonding and film resistors with manual trim for scaling and null adjustments. Potentiometers were included in the breadboard but would not be used in a final version.

3.3.19 Spark Driver; Board No. 27; Valve Driver; Board No. 28 (Figure 23)

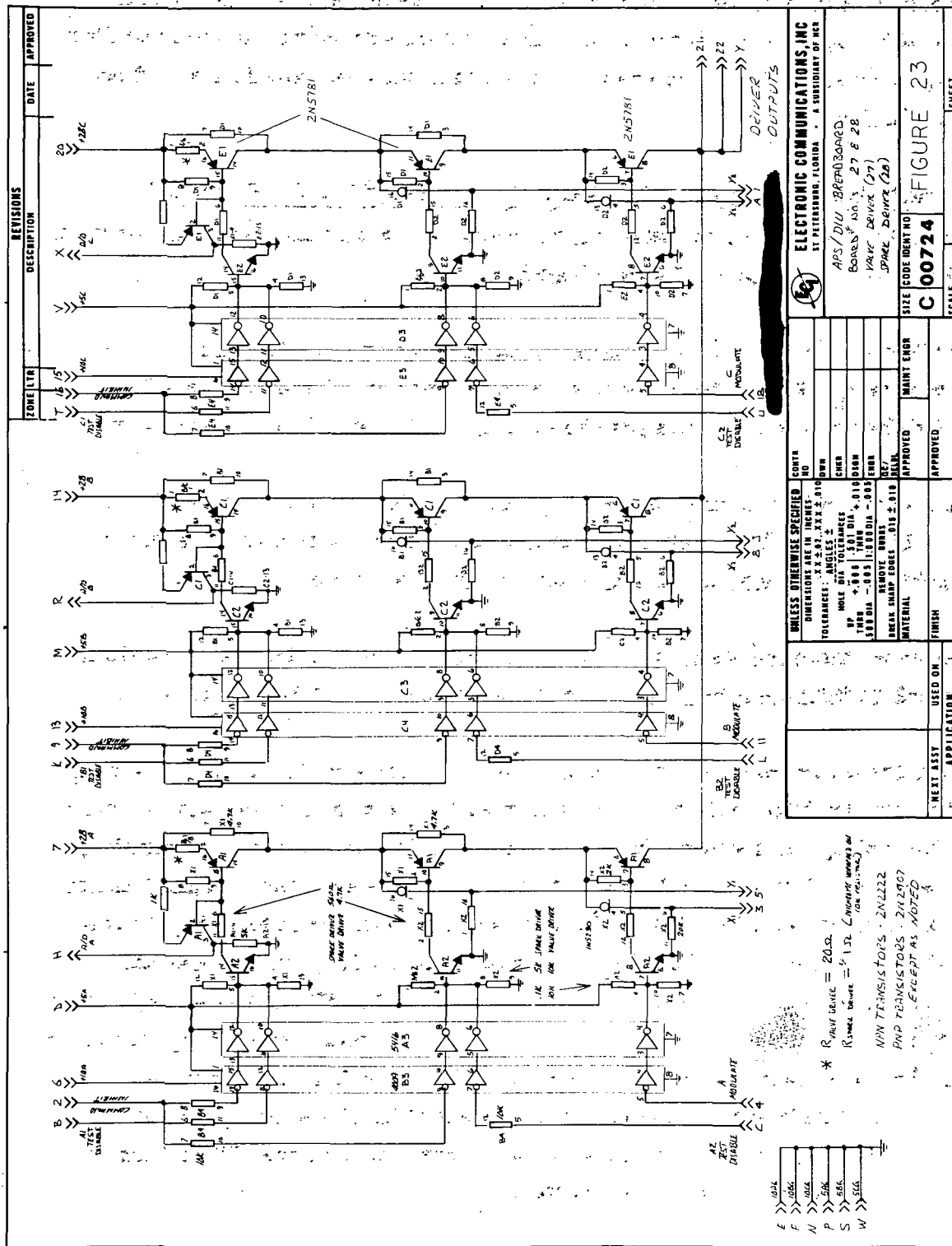
The Spark and Valve Drivers are identical in schematic configuration with the exception to circuit values because of the different load capabilities.

The Spark Driver was assumed to require 1 ampere drive and the Valve Driver was assumed to require 50 ma drive capability. Both of these may be altered in either direction by altering resistor values or the boards may be interchanged as required.

Each board is comprised of three drivers each of which is associated with a Firing Logic set. Each driver has three transistors in series two of which are intended for failure inhibit and the third for 'modulate' or turn-on of the driver.

The drivers are interfaced with CD4009's configured for a TTL interface to 5416's. These control 2N2222 drive transistors which turn on the PNP 2N5781 drivers.

Each driver has a current-monitoring resistor which is one ohm for the Spark Driver and 20 ohms for the Valve Driver. Here, the on-state would indicate one volt for each driver. This voltage is interfaced to the monitoring A/D Converters with a transistor and two resistors. Referring to the schematic, transistor A1 at pins 1, 2 and 3 has a 1K resistor in series with its emitter and it is tied to 28V(a). Assuming that the two PNP's will have near-tracking base-emitter voltages, the voltage then across the current-sensing resistor and the drive transistor (A1-14, 15, 16) emitter-base junctions is fixed by the driver load. Since this same voltage is across the monitoring transistor (A1-1, 2, 3) base emitter plus 1K resistor string, the 1K resistor then becomes a current determining element for the collector current which flows through the 5K resistor. The scaling, then is set based on 1 volt across 1K or 1 ma; 5K at 1 ma is 5 volts which is the input to the A/D Converter.





3.3.20 Line Pressure Amplifier/Comparator; Board No. 30 (Figure 24)

The function of this circuit is to monitor pressure transducers which indicate fuel and oxidizer line pressures. As with the previously discussed Chamber Pressure Amplifier, a strain-gauge nominal value of 511 ohms was assumed and the amplifiers are nominally scaled at approximately 1 volt per 10 ohm change. And, as before, the amplifiers feed A/D Converters and the comparators shown.

Functionally, the circuit senses a drop in pressure below some acceptable level yet to be defined. However, once the comparators sense this drop, the information is fed to the Emergency Shutoff Monitor to disable the engine. The ESO data is the outputs of the NOR gates B1, B2 and B3. The remaining gates are used for inverters which feed the binary status to the status monitor for reporting to the data bus.

The logic records hard failure states and the A/D Converters Monitor slower degradation.

3.3.21 A/D Clocks; Board No. 31 (Figure 25)

The function of this board is to provide a 12.5 KHz clock for the tracking A/D Converters. There are three generators each sensing a different "end-of-word" source at 50 KHz and each divides this frequency by 4. Pulse shaping is accomplished with an RC circuit feeding the inverters D1, D2 and D3 such that the pulse width is approximately two (2) microseconds. The remaining gates are used in a buffer configuration for driving the lines to the A/D Converters.

In addition, there is inter-synchronization added between the three generators using 150 pf capacitors cross-coupled to the reset lines of the flip-flop dividers. This insures that one of the generators becomes "command" and that the remaining will slave-synchronize. It is academic which generator has command or that synchronization truly exist. The feature was added for test and monitoring convenience.

3.3.22 Status Monitor Timing and Control; Board No. 32 (Figure 26)

This circuit both enables the Status Monitor Multiplexers and sets up the timing for outputting the Status Monitor word selected to the Polar RZ Modulators.



The Status Monitor word request command inputs to the inverters as shown on the schematic from the ISVC circuitry. The inverter outputs are fed to the multiplexers and a set of Exclusive OR's. Here, additional information verification is performed in that the Exclusive OR tree will only respond if the number of request commands is odd (1, 3, 5, etc.). One command is truly valid. The probability of receiving three commands is extremely remote and receiving two simultaneous commands is rejected.

Once the command is received, latch B1/B1 is set and begins the sequence as illustrated in Figure 27, the Status Monitor Timing Diagram.

The first pulse outputted is the "status monitor load" pulse which is generated by the state of E4-Q3 and the fact that a command has been received. This loads the information into the Status Monitor serial registers of Board 14. With this event, a two bit counter is enabled which counts off 40 microseconds or two "end-of-word" cycles. When X1 and X2 of D4 reach the states of low-high respectively, the Status Monitor clocking and Polar RZ clocking trains are developed. These are used to shift the data out. The end of this event is decoded to reset the B1/B1 latch back to the standby state.

An alternate mode is operated during the "Self-Test" sequence of the APS/DIU. Because the self-test sequence does iterate all the system commands, the Status Monitor Timing and Control module must ignore this function or all status words would be outputted. Consequently, the B2/C1 latch recognizes the self-test command and is armed to inhibit latch B1/B1 from reacting to the self-test generated words.

Once the self-test is complete, a status word is available at the multiplexer and the Test Sequencer issues a "load/send" pulse to the Status Monitor. At this time, the registers are loaded and latch B1/B1 initiates the send cycle as before.

The inverters E3 that output to pin S shape up the clock pulses to the registers and the C2 X-OR gate and additional E3 inverters provide sufficient delay, along with the diode-resistor-capacitor network to the C3 inverters to provide the Polar RZ clock. Here, it is insured that the data and clock skewing is aligned such that the outputs of the Polar RZ provide the proper waveforms.



3.3.23 Subroutine Word Test Read Logic; Board No. 33 (Figure 28)

This logic is part of the "Test Sequencer" function and operates only during the "self-test" exercise.

As a function of the self-test, a subroutine is iterated several times that inserts all the commands of the APS/DIU into the front end of the ISVC circuits. The results are (or should be) a series of decoded commands providing the ISVC circuits are performing correctly.

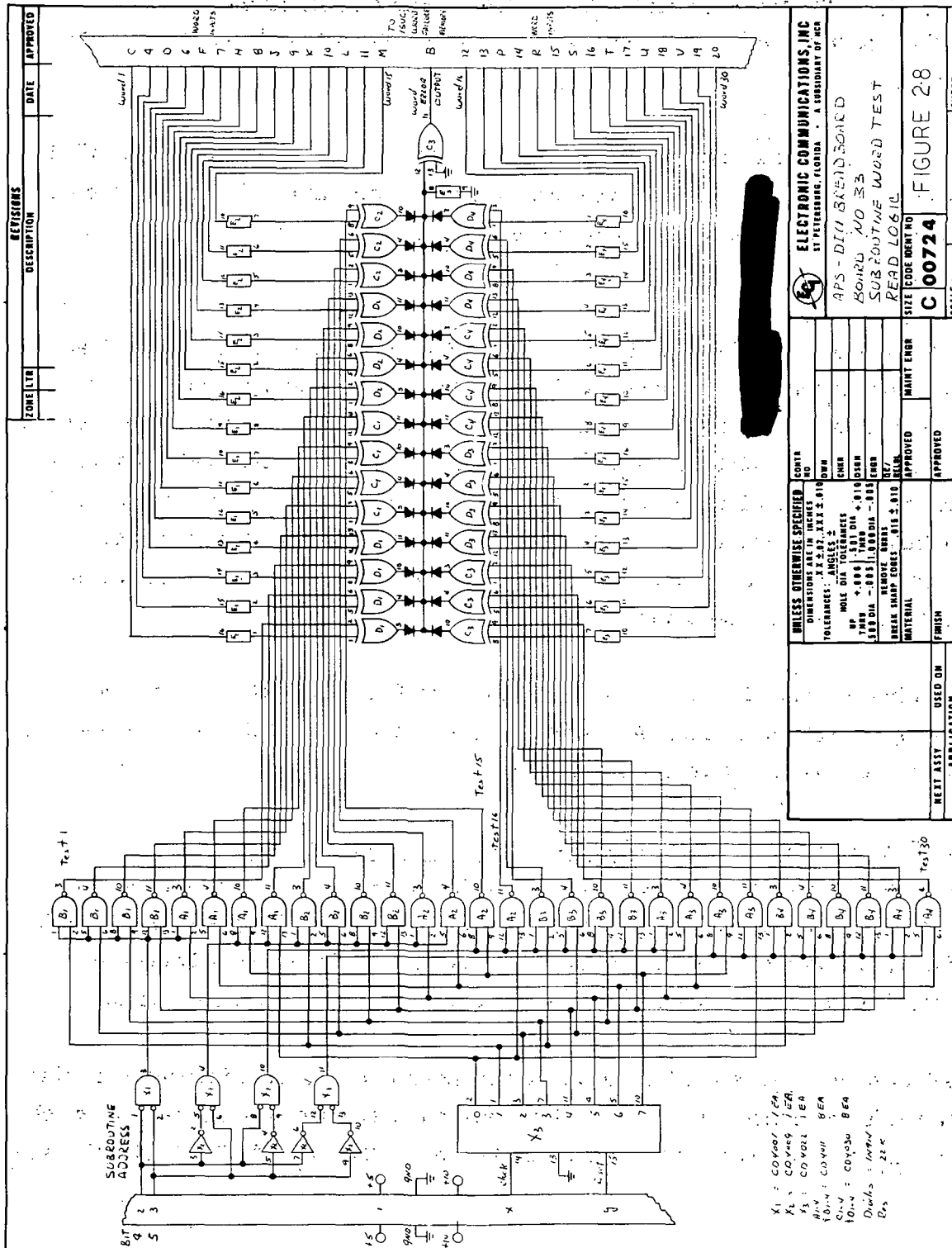
As these commands are iterated, the Subroutine Word Test Read Logic verifies that each word appears as it should and that there is only one command at that time, (a single 'zero' in a field of one's). As the commands are generated by an address counter on the Subroutine Control Logic, Board No. 36, the shift register X3 is clocked while the gate logic of X1 and X2 decode the states of bits 4 and 5 of the address counter. The combinations of these outputs are Nanded in the test gates such that there is correspondence in the 'zero' out of the test gates with each 'zero' sensed at the word input. That is, test 1/word 1, test 2/word 2, etc.

For a continuous normal operation, the outputs of the Exclusive-ORs will remain at zero during the word test time. A failure inputs a 'one' or high at the diode OR function which drives the output "word error" gate C3.

3.3.24 Test Sequencer Control Memory; Board No. 34 (Figure 29)

The function of this board is to place the APS/DIU in a series of unique configurations such that specific tests may be performed to verify individually the given portions of the redundancy. As with the rest of the Test Sequencer logic, this board only operates during the "self-test" exercise and, in fact, it is powered down at all other times.

The control memory receives its clocking information from the Test Sequencer Timing and Control logic, Board No. 35. The clock drives the synchronous counter C1, which generates the address data for the Read Only Memories D1, D2 and C2. Table IV is the



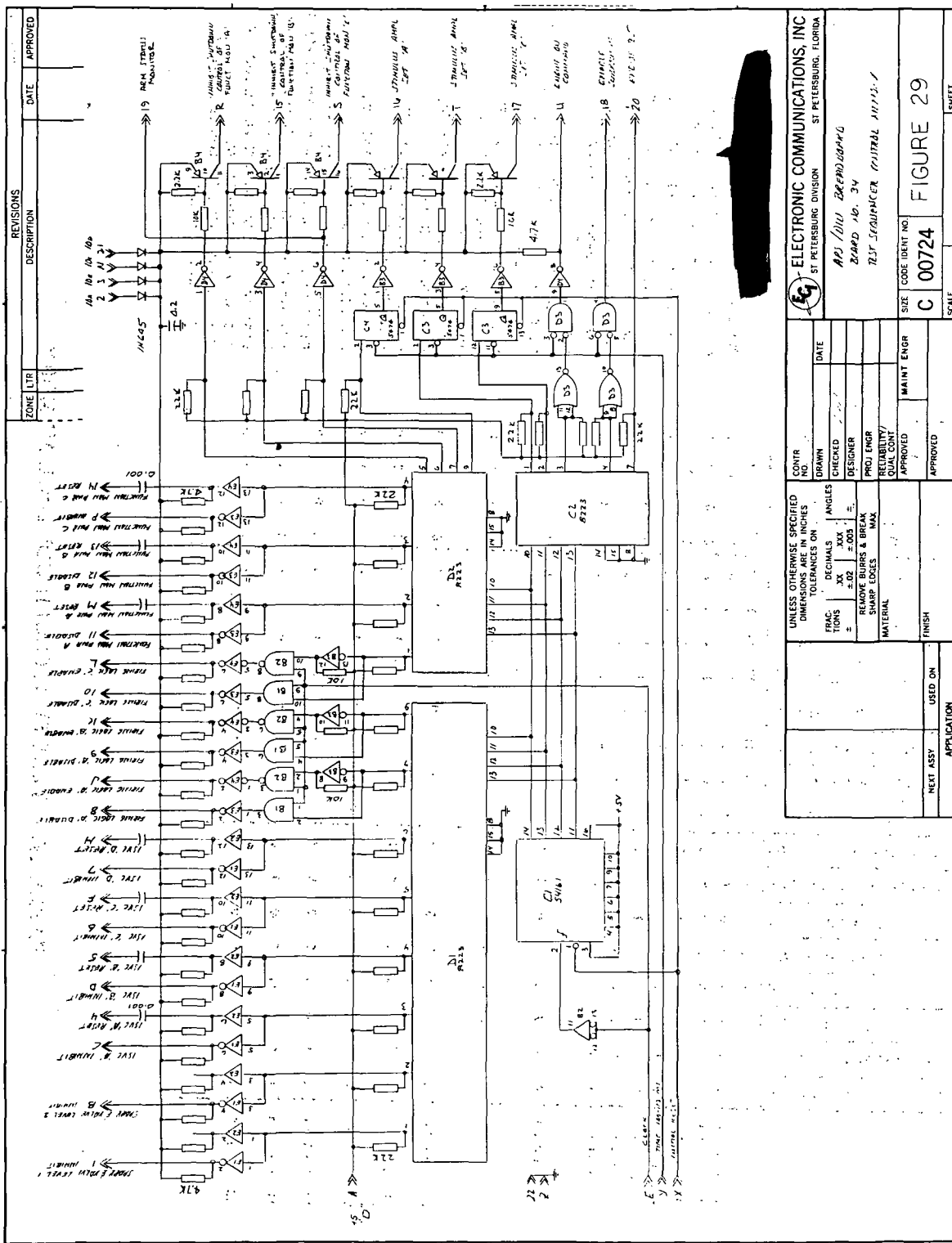


FIGURE 29. TEST SEQUENCER CONTROL MEMORY



	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
SPARK & VALVE LEVEL 1 INHIBIT	1	1	1	1	0	0	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENABLE SUBROUTINE
SPARK & VALVE LEVEL 2 INHIBIT	1	1	1	0	1	0	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
ISVC 'A' DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	STIMULUS AMPS 'A'
ISVC 'B' DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	STIMULUS AMPS 'B'
ISVC 'C' DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	STIMULUS AMPS 'C'
ISVC 'D' DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
FIRING LOGIC 'A' DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENABLE SUBROUTINE
FIRING LOGIC 'B' DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
FIRING LOGIC 'C' DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENABLE SUBROUTINE
FUNCTION MON 'A' PWR DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
FUNCTION MON 'B' PWR DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
FUNCTION MON 'C' PWR DISABLE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
INHIBIT CONTROL FM 'A'	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
INHIBIT CONTROL FM 'B'	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
INHIBIT CONTROL FM 'C'	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
STIMULUS AMPS 'A'	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
STIMULUS AMPS 'B'	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
STIMULUS AMPS 'C'	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
ENGINE TURN-ON	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON
ENABLE SUBROUTINE	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	0	0	0	0	1	ENGINE TURN-ON

RUN SUBROUTINE TO TEST ISVC C & D
 RUN SUBROUTINE TO TEST ISVC B & D
 RUN SUBROUTINE TO TEST ISVC B & C
 RUN SUBROUTINE TO TEST ISVC A & D
 RUN SUBROUTINE TO TEST ISVC A & C
 RUN SUBROUTINE TO TEST ISVC A & B
 READ SPARK/VALVE LEVEL 1 SET 'A';
 READ AUTO TURN-OFF: READ FM'S
 REDUN PWR B + C
 READ SPARK/VALVE LEVEL 2 SET 'A';
 READ AUTO TURN-OFF: READ FM'S
 REDUN PWR A + C
 READ SPARK/VALVE LEVEL 1 SET 'B';
 READ AUTO TURN-OFF: READ FM'S
 REDUN PWR A + B
 READ SPARK/VALVE LEVEL 2 SET 'B';
 PRESS THRESHOLD TEST 'A'
 READ SPARK/VALVE LEVEL 1 SET 'C';
 PRESS THRESHOLD TEST 'B'
 READ SPARK/VALVE LEVEL 2 SET 'C';
 PRESS THRESHOLD TEST 'C'
 INITIATE ENGINE-ON CMND TO FIRING LOGIC 'A';
 RECORD FM 'A' SHUTDOWN 'A' & TURN ON 'B' SET
 INITIATE ENGINE-ON CMND TO FIRING LOGIC 'B';
 RECORD FM 'B' SHUTDOWN 'B' & TURN ON 'C' SET
 INITIATE ENGINE-ON CMND TO FIRING LOGIC 'C';
 RECORD FM 'C' SHUTDOWN 'C';
 INITIATE STATUS MONITOR LOAD/SEND; POWER
 DOWN TEST SEQUENCER

TABLE IV. TEST SEQUENCER CONTROL MEMORY



truth table for these memories detailing the controls exercised according to address as well as the test performed during the given configuration.

The "time 100-102 ms" input, shown on the schematic, provides a delay configuration or command at 100 milliseconds after the initial configuration was programmed by the control memory. This is a "settling" time to minimize transient responses introduced by the Test Sequencer forcing function.

3.3.24.1 Truth Table

The following discusses the control memory truth table and those specific functions that are exercised during each step.

STEP 1. The subroutine is exercised here while ISVC logic sections A and B are powered down to verify sections C and D. The Subroutine Word Test and Read Logic (Board No. 33) and ISVC Encoder (Board No. 38) would be exercised during this period to memorize status.

STEP 2. The same as Step 1, except ISVC B and D are verified.

STEP 3. The same as Step 1, except ISVC B and C are verified.

STEP 4. The same as Step 1, except ISVC A and D are verified.

STEP 5. The same as Step 1, except ISVC A and C are verified.

STEP 6. The same as Step 1, except ISVC A and B are verified.

STEP 7. Several tests are performed during this step. The first level (top) of the Spark and Valve drivers "A" are inhibited while the second level is "on"; the engine is fired and the status of the drivers is measured and recorded on Board No. 37; the automatic turn-off feature of the Firing Logic "A" is checked and recorded and the function Monitors are verified for proper output using only two of their three power supplies (B&C). During this test, the 'control' of the Function Monitors is inhibited at the Power Enable/Disable logic so that the system does not switch over to the next backup ("B" in this case) because the engine did not react.

STEP 8. Similar to Step 7, except level 2 is inhibited and the Function Monitors are operated on power supplies A and C.



- STEP 9. The same as Step 7, except the operation is on "B" drivers and Firing Logic and the Function Monitors are operated using power supplies A and B.
- STEP 10. Similar to Step 8 except, instead of testing Function Monitors, the Pressure Amplifiers "A" are stimulated and the thresholds verified and recorded on Board No. 38.
- STEP 11. Similar to Step 10 except "C" drivers are tested at level 1 along with Firing Logic "C" and the "B" Pressure Amplifiers are stimulated for threshold test.
- STEP 12. The last driver test with inhibit on level 2 of "C" plus the "C" Pressure Amplifiers are stimulated.
- STEP 13. Steps 13, 14 and 15 are intended to exercise and witness the automatic shutdown and switchover of the Firing Logics from the commanded set to the next backup and then to the "all off" condition.

3.3.25 Test Sequencer Timing and Control Logic; Board No. 35 (Figure 30)

This logic generates the fundamental timing and control for the Test Sequencer processes. It contains logic which is powered full-time to recognize the turn-on command and the automatic turn-off as issued from the control memory. In addition, there is an initializer circuit that is active during APS/DIU power "on" and end-of-test. This initializes the unit such that Firing Logic "A" is on and insures that the Redundancy Override Reset has been issued to reset the power interrupt circuits to their normal configuration.

Upon receipt of the "self-test" command, latch D1/D1 sets such that D1-6 is high which enables the Test Sequencer power supply. In addition, the positive transition at this triggers the monostable C1. This one-shot outputs a pulse of approximately 100 milliseconds which is used for the "initial reset" of all the Test Sequencer functions. (Note that the timing elements are slow and, at times, appear to be randomly selected. Some are. The timing is configured to be sufficient to do the operation without approaching those time-increments where propagation, response time, etc., become interfering problems; 100 milliseconds, for instance is a long time for resetting logic devices; however, it allows sufficient time for the power supply to stabilize before any test



sequences are started. Further, there is no real requirement for exercising the self-test sequence "in a hurry.")

After the initial reset pulse, the reset pins of the two monostables B1/B1 are released and the clock cycles are started. Each monostable is timed for one millisecond for a clock frequency of 500 Hz. The clock then drives the timing registers B4, A4, C3 and B3 to generate the sequencer timing. For each step of the control memory, the timing registers clock through 200 milliseconds to create the various read pulses caused by the stimuli injected into the system. The times and functions are detailed on the schematic and their use will be discussed with each applicable function.

The timing registers are interrupted and inhibited by the Subroutine Control Logic which creates its own timing. During this time, the system configuration is fixed and the subroutine will iterate through the input commands for ISVC circuit verification. Following each iteration, control will return to the Timing and Control board for continuation to the next step.

At the end of the test sequence, the control memory will enable gate D2, which selects a pulse from the timing register, to reset latch D1/D1. At this time, the Test Sequencer power supply is shut down and the initiator circuit will reset the system to the starting normal configuration.

3.3.26 Subroutine Control Logic; Board No. 36 (Figure 31)

This board generates the timing for formulating and outputting the ISVC commands and the read pulses required for data verification. It is enabled by the Test Sequencer Timing and Control Logic at the appropriate time and it will inhibit the control logic until it has completed one iteration of the command set.

A "subroutine enable" command is received on pin 2 which is two milliseconds in duration. The state prior to this pulse is used to reset the address counter B1 and the sequence register of the Read Logic Board No. 33. The pulse transition is the initial



trigger into the re-triggerable monostable C4 whose output state returns an inhibit signal to the control logic. The inhibit signal, in turn, stops the activity in the control logic which freezes the "subroutine enable" to a high and it is not permitted to clock off until the one-shot state returns to a high at the output of C2. With continued activity in the subroutine logic, a retrigger is regularly provided from the Subroutine Timing Register D3 pin 6. Once the iterations are complete, however, gate B4 flags the 'last-word-through' which initially returns control to the control logic and, once the remainder of the 'enable subroutine' command has been cycled through, the timing register will cease retriggering C4 which will time out to complete the return-control cycle. A second function of C4 is to yield a 'return-control' signal to the control logic should the timing logic fail within the Subroutine Logic. This prevents lock-up in a non-functioning subroutine. This could happen if an ISVC circuit set were to fail while under test such that the Subroutine Logic did not receive either clock or end-of-word information. Here, the D3 register would cease clocking and, therefore, the required retrigger would be missed.

The timing sequence is illustrated in Figure 32 Subroutine Timing Diagram. As can be seen from this diagram, the shift register is made to load and shift on alternate 20 microsecond time slots as determined by the JK D4. And, during the shift cycle the address counter is made to increment to the next word. Also, during the same word-frame time that is used to load new data, a "read" pulse is generated such that the results of the last word entered into the ISVC can be verified.

The discrete pulses for clocking the address counter, loading the register, retriggering the one-shot, etc., are derived from the 8-bit Shift Register D3 which is clocked by the system clock after it has been divided-by-two at the C1 flip-flop. This spreads these operations out over a period of 16 microseconds of the 20 microsecond word frame length. NOR gate A4 insures that the timing shift-clock is the same phase for each frame by resetting C1 at each end-of-word.

The counter B1/C1 generates the address for the ROM located at A1 which is configured for a Signetics Device 8223. However, since the APS/DIU commands were assigned

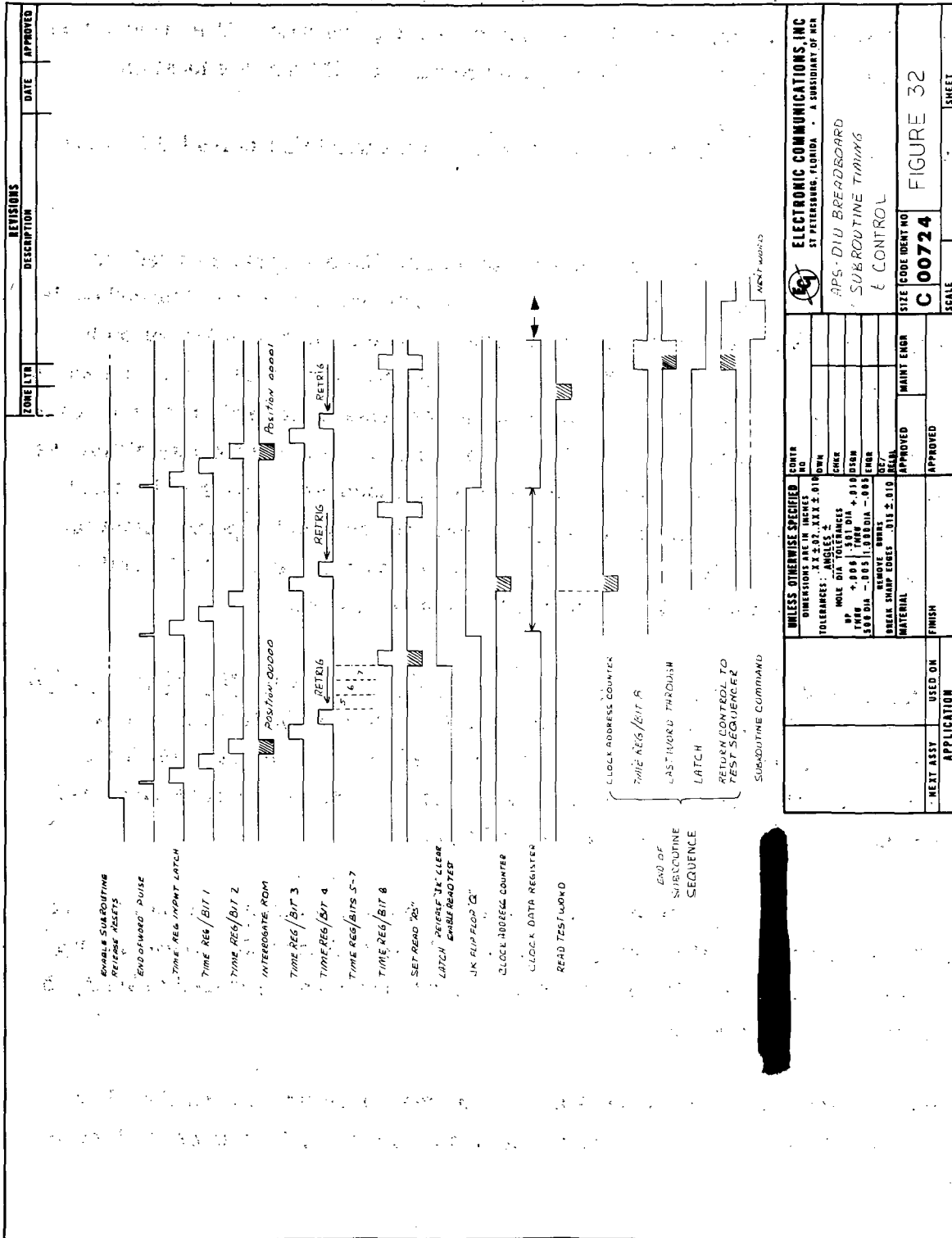


FIGURE 32. SUBROUTINE TIMING and CONTROL



(initially), to a straight binary 00001 to 11101, the RAM was removed and jumpers inserted such that the address itself is used for the word generation. The provision is there, though to re-assign the word format and program a ROM for this location.

B2 is the parity generator which assigns odd parity to the word that is loaded into the shift register.

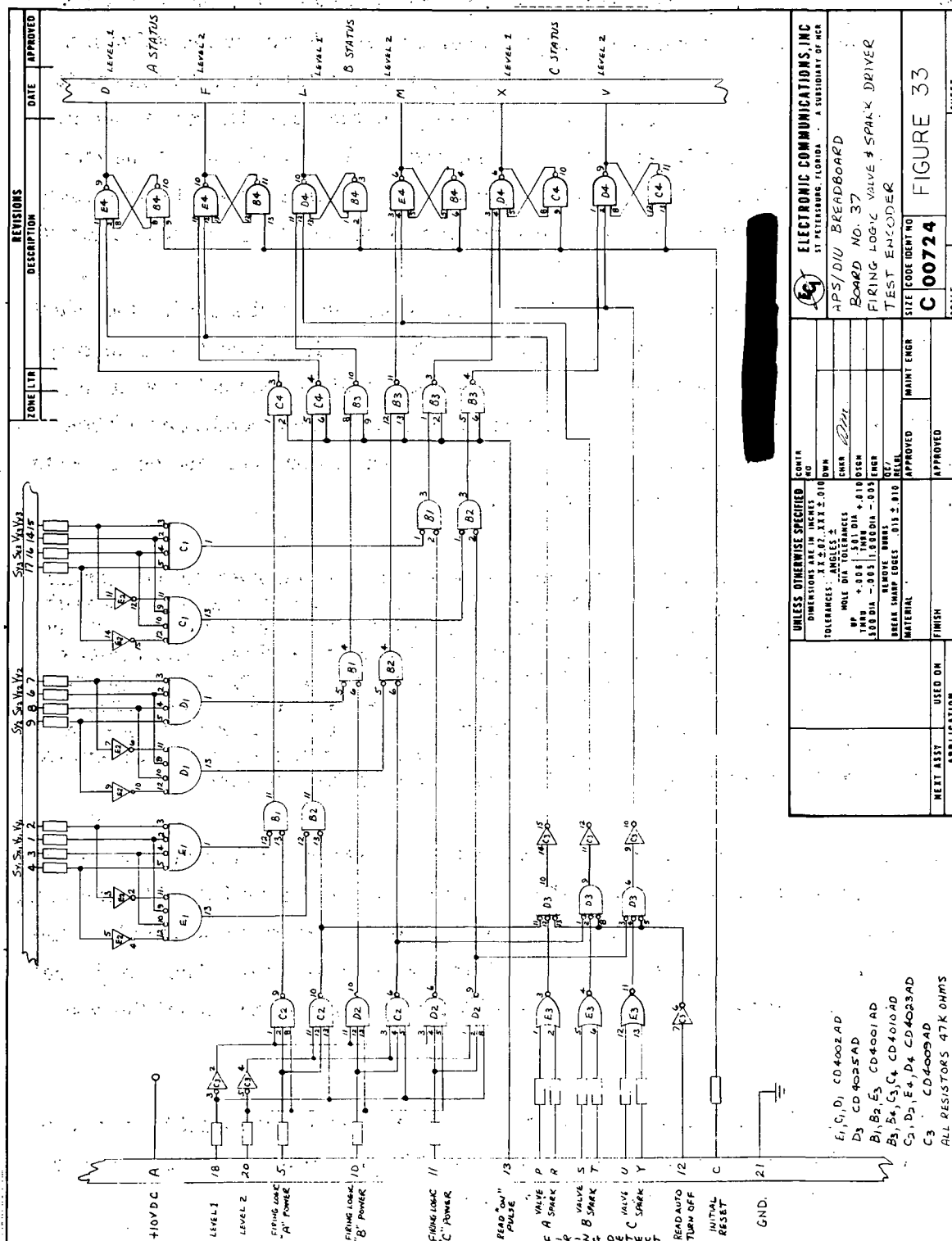
The output of the shift register at A3 drives a set of four buffer-inverters used for interface to complementary transistor sets. The transistors are used to "force" one's and zero's at the input of the ISVC input registers regardless of what information is there at the time. Normally during this time, the input word to the ISVC circuits should be "all zero's" to provide clock and word sync. A zero enters the one's registers as a low and the zero's register as a high. The single exception is the odd parity bit for the incoming all-zero word which is a high for the one's register and a low for the zero's registers. In any case, the Subroutine Logic output will force in the proper state for the word injected and the ISVC will be made to ignore incoming data. The incoming clock, however, is used to clock the test word into the registers.

3.3.27 Firing Logic; Valve and Spark Driver Test Encoder; Board No. 37 (Figure 33)

The purpose of this logic is to "read" and record the results of the test sequences applied to the Firing Logic and Spark and Drivers in steps 7 through 12 of the Test Sequencer Control Memory. The status of the driver transistors is measured as well as the automatic turn-off feature of the Firing Logic.

Gates E1, D1 and C1 are the "level 1" and "level 2" test gates which view the states of 'X' and 'Y' outputs of the Valve and Spark Drivers shown in Figure 23. Here, during the test, one level at a time, is inhibited while a firing command is issued to verify the status of the inhibit transistors.

For example, with level 1 inhibited (Figure 23) the top driver transistors should be "off" and open. The center transistors are on and the modulate transistor (bottom) is





turned on when a firing command is programmed. During this state, the voltage ratio between the 4.7K resistor (located across the top transistor) and the load is measured. At this time, the current through the load is approximately 5.3 ma for the Valve Driver and 5.9 ma for the Spark Driver (both values being far below that current required to operate the load). The voltage across the load, then, for the Valve Driver is 100 mv. The constant-current diodes located at emitters of the level 2 transistor and the modulate transistor would then both have low voltages at their inputs and their load resistors would output logic 'zero's' if the level 1 transistor was open and not leaky or shorted.

A similar situation exists during level 2 inhibit except that the level 2 constant-current diode will output sufficient current (approximately 500 μ a) to let its load resistor output a logic high (10V). The constant-current diode at the modulate-transistor would again be current-inhibited such that the 'X' output would be a low. This condition verifies that the level 1 transistor came on and that the level 2 transistor is off and open. Both tests verify that the modulate-transistor is 'on'.

NOTE: The current measurements that are made with the A/D converter monitoring the current of each branch of both the Valve and Spark Drivers yield a wealth of information about the drivers other than just the "on" load current. These data are not recorded during the "self-test" but they could be. The various currents measured during the different level-inhibits and engine firings are essentially indicative of the transistors off-leakages as well as the states of the NPN controlling transistors and their sinking currents. A table of data could be established as a troubleshooting guide to pin-point specific deteriorations different from nominal performance in the driver system.

With the proper states outputted from the "X" and "Y" points of the drivers, the gates E1, D1 and C1 will output a high during the read access time (Figure 33). The two level tests are distinguished by the decoder logic at the left of the schematic which views the level test in progress as well as which Firing Logic set is under test. The "read 'on' pulse" at pin 13 enables a set of six gates to set a group of latches to record the test results.

In addition, gates E3 and D3 are employed to verify the automatic turn-off feature of the Firing Logic under test. Here, a read pulse is issued after the firing pulse should be over. If it still exists, the recording latches are set.



The recording latches yield the following combined information in a two-bit code for each Firing Logic/Driver set:

0	0	level 1 & 2 & auto turn-off o.k.
0	1	level 1 test failure & turn-off o.k.
1	0	level 2 failure & turn-off o.k.
1	1	both level 1 & 2 failed or turn-off failed

3.3.28 ISVC and Pressure Threshold Test and Encoder Logic; Board No. 38 (Figure 34)

This board has two sets of logic on it; each recording separate tests.

The first set, on the left of the schematic, records the status of the ISVC tests where the input commands are cycled through the ISVC circuits with the sections powered down in pairs.

The inputs on pins A, B, C and D are control memory inputs indicating which ISVC logic sets are powered. The remaining inputs are the word errors from the logic on Board No. 33 and the read pulse from the Subroutine Logic Board No. 36. The word errors are registered and recorded in the latch set in accordance with the ISVC pair that the errors occurred in. Gates B1, B2, B2 and B2 view the latch indications and decode and output which ISVC circuit(s) have failed.

The logic at the right of the schematic reads and records the status of the pressure amplifiers into a two-bit code.

Each set of "A" amplifiers for the chamber pressure and line pressure are stimulated with an offset voltage as is "B" and "C" in sequence. The status of their corresponding output comparators are logically sampled first in the unstimulated mode then in the stimulated mode to verify their performance. The information is recorded in the following two-bit code:

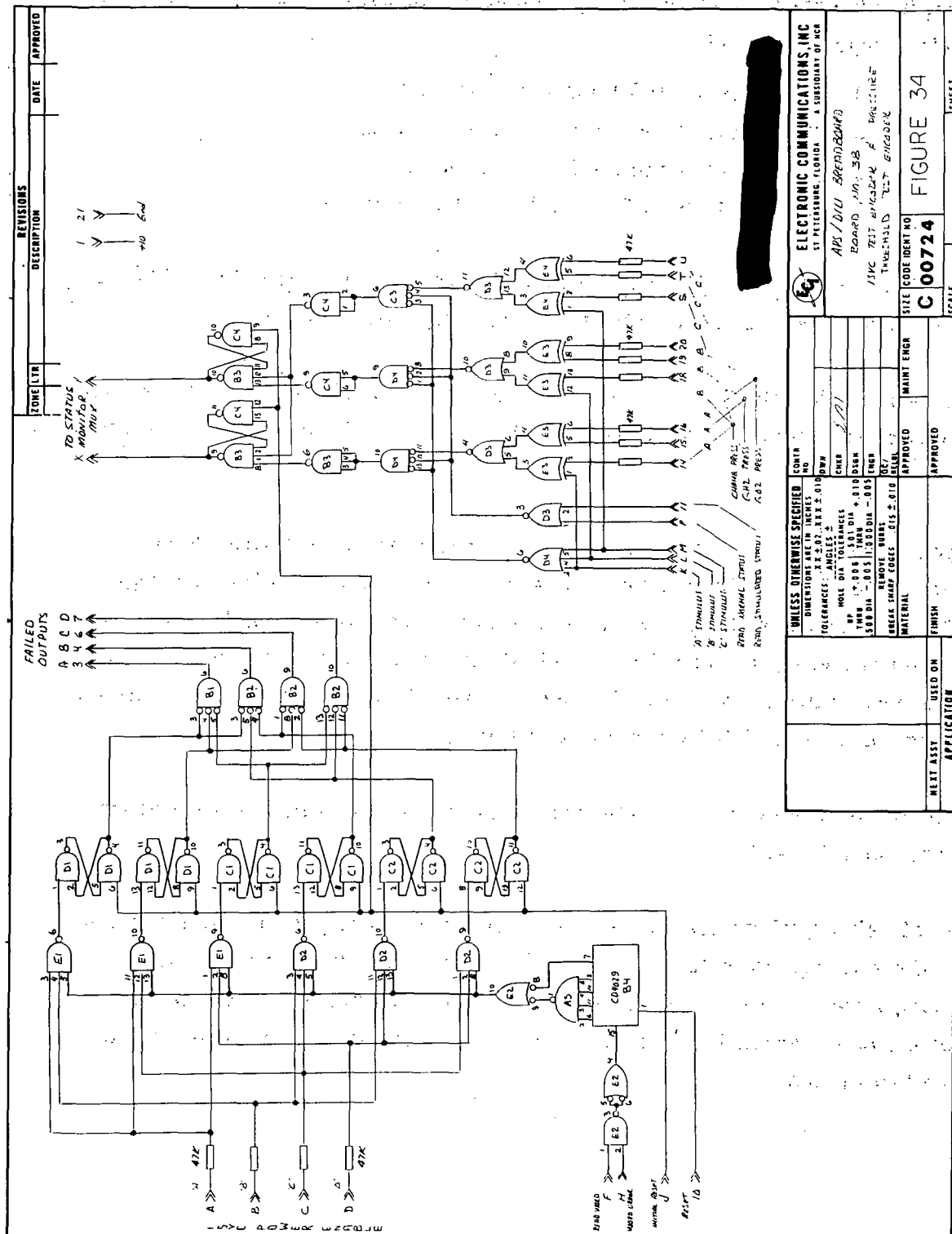


FIGURE 34. ISVC TEST ENCODER and PRESSURE THRESHOLD TEST ENCODER



0	0	all amplifiers performing normally
0	1	an "A" amplifier failed
1	0	a "B" amplifier failed
1	1	either an "A" amplifier and a "B" amplifier failed or a "C" amplifier failed or one each of all three failed

**3.3.29 - Function Monitor Performance and Redundancy Test Encoder;
Board No. 39, (Figure 35)**

This logic verifies that the Function Monitors perform normally when operated with only two of their three input supplies. Each powers a similar but separate section where the outputs are majority-voted. In addition, this logic verifies that the automatic switch-over feature performs as expected among the Firing Logic sets.

The logic to the left of the schematic verifies the Function Monitors performance during steps 7, 8 and 9 of the Test Sequencer Control Memory. Here, each function monitor has one of its sections power-disabled at the same time that the Firing Logics are exercised. However, because the drivers are inhibited, the sensors will feed back "failure" information to the Function Monitors indicating that the set is inoperative. Although the Function Monitor Control has been inhibited from controlling the Firing Logic configuration, the outputs can be measured in response to the sensor indications.

These outputs are verified both prior to and during the "engine-on" activity by the "read normal state" and "read sensing" pulses. The Function Monitor outputs are high prior to stimulation and low during stimulation to indicate system failure. The information is stored in two latches for the following two-bit code:

0	0	Function Monitor redundancy o.k.
0	1	a Function Monitor failed with "A" power off
1	0	a Function Monitor failed with "B" power off
1	1	a Function Monitor failed with "C" power off

Which Function Monitor failed is not determined but the problem area is defined by the limited code.



The remaining logic on this board verifies the switchover performance of each Function Monitor/Firing Logic/Power Enable/Disable set.

Since the Drivers are inhibited during the self-test, the Function Monitors are permitted to use their "failure" information to cause the required switchover. The control memory initiates the system into the "A" set and the engine-on command is issued. The system should then switch over to the "B" set since there was no engine reaction. The engine-on command is again issued and the system should switch once more to the "C" set. A third cycle should witness shutdown of the "C" set.

After the "A" 'failure' is witnessed good or bad, the logic is forced into the "B" configuration for the next test. Again, after the "B" test good or bad, the logic is forced into the "C" configuration for the second test. And, in turn, the "C" configuration is programmed for the last test. The two-bit code, then, identifies the following:

0	0	Function Monitor and switchover performance normal
0	1	system did not switch from "A" to "B"
1	0	system did not switch from "B" to "C"
1	1	either the switchovers from "A" to "B" <u>and</u> "B" to "C" did not occur <u>or</u> "C" did not shut down

3.3.30 Power Interrupt Module A or B: Board No. 40 (Figure 36)

The function of these modules is to provide power-interrupt capability for both the Test Sequencer operation as well as the Redundancy Override commands inputting to the system.

The power interruptions are provided and controlled by latches, placed in either the "on" or "off" mode, which feed open-collector buffers to interface with transistor switched. Because the power interrupted is 10 V, the voltage drop in the switches is inconsequential.

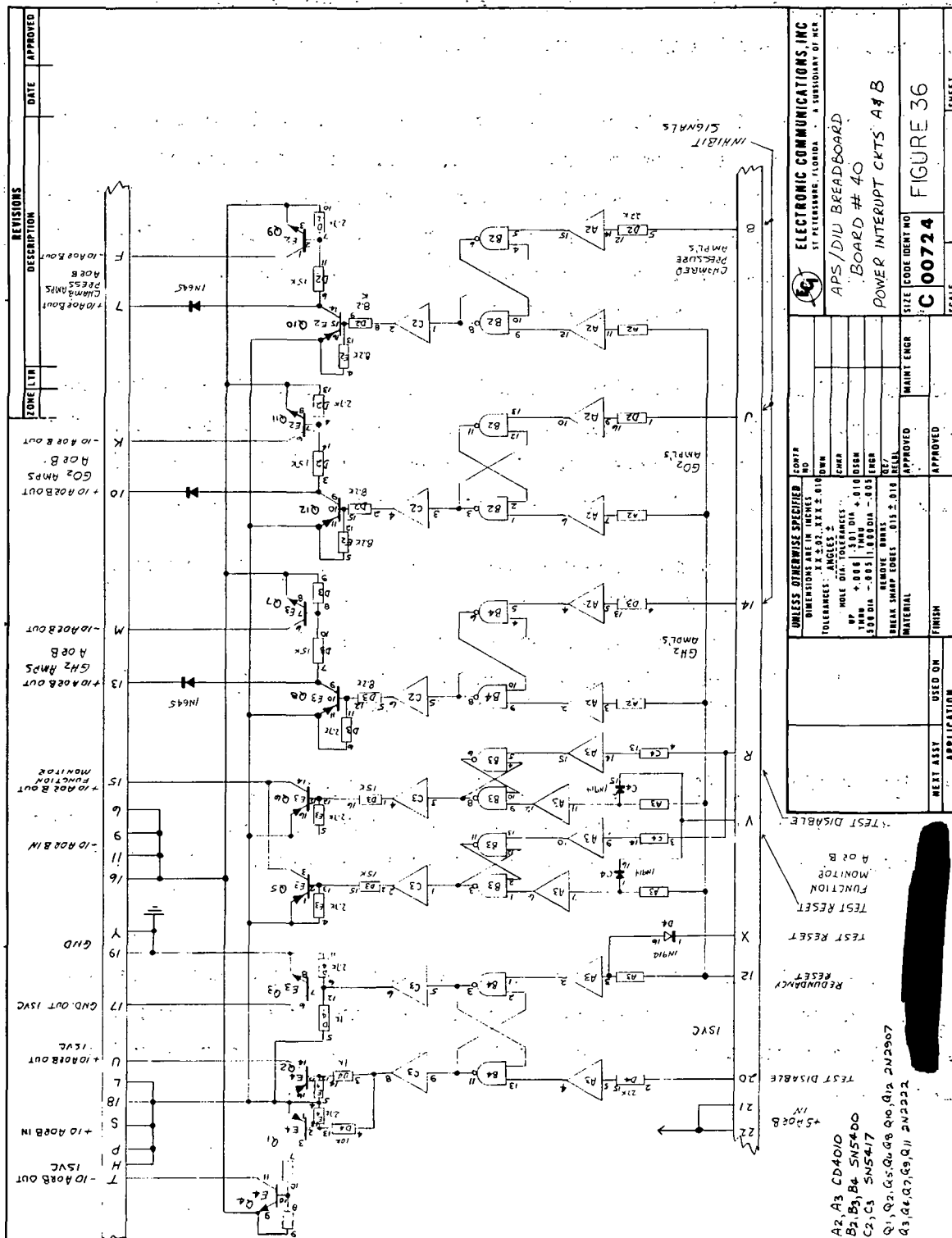


FIGURE 36. POWER INTERRUPT CIRCUITS A & B



3.3.31 Power Interrupt Module C and D; Board No. 41 (Figure 37)

This board is identical to Board No. 40 with the addition of another ISVC interrupt circuit which provides power to the "D" channel.

3.3.32 Power Supplies

3.3.32.1 Power Supply A (Reference Figure 38)

Power Supplies A, B, and C are identical. See Table V.

Output Voltages & Loads	+10 V, 130 ma	-10V, 8 ma
	+10 V, 230 ma	-10V, 30 ma
	+15 V, 170 ma	-15V, 100 ma
	+ 5 V, 1.5 amp	
Input Voltage	24 to 32 VDC	
Ambient Temperature	-55°C to 125 °C	
DC Isolation	>10 ⁸ ohms input to output	

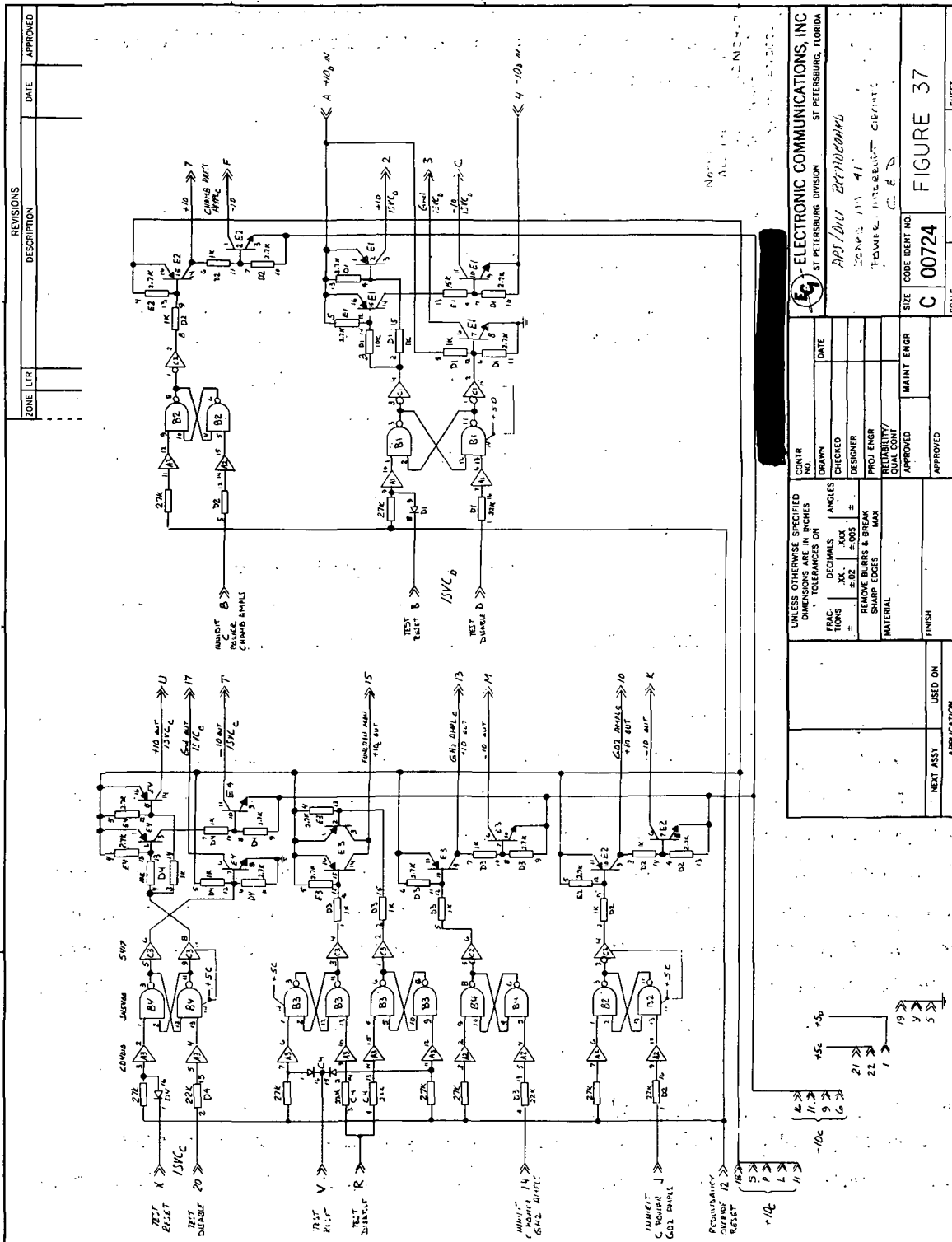
TABLE V. POWER SUPPLY A(B&C) REQUIREMENTS

3.3.32.1.1 DC-to-DC Converter

The primary function of the inverter circuitry is to provide DC isolation from the nominal 28 volt power source and to establish output voltages which are near the optimum levels to power the associated absorptive regulators. This circuit is comprised of an EMI filter with a reverse-polarity diode and a saturating-core inverter with associated rectifiers and filters. The shunt diode across L1 in the EMI filter prevents a large voltage spike from being developed when the inverter core saturates and the inverter commutates. The operating frequency of the inverter varies from 13.7 to 17.8 KHz for input voltages of 24 volts to 32 volts.

3.3.32.1.2 Isolated ±10 Volt Supply

A regulated supply of nominally +10 V is generated by an absorptive type regulator utilizing a μ A723 precision voltage regulator and a series pass element. This type of





design is characterized by excellent transient response and good regulation against load and input voltage variations. Short circuit protection is simply provided by sensing the voltage drop across a small resistor (2.7 ohm) which is proportional to the load current. When this voltage exceeds approximately 0.6 volt corresponding to an overload condition, the base current of the pass element is decreased and the regulator limits the output current to a safe value in excess of the normal maximum of 130 ma.

Since the regulation on the -10 volt, 8 ma, supply is not critical, a simple one transistor regulator is adequate. A limiting resistor (180 ohms) protects the active components from a load short.

3.3.32.1.3 ±15 Volt Supply

The operation of the +15 volt, 170 ma, regulator is identical to that of the isolated +10 volt regulator. The -15 volt regulator utilizes the +15 volt regulated voltage as a reference. This eliminates the need for a reference zener and provides automatic shutdown on the negative supply when the positive supply drops to zero. Short circuit protection is provided by sensing the voltage across a 2.7 ohm resistor. When the voltage exceeds the base-to-emitter breakdown of a 2N2907A transistor, the transistor conducts, thus reducing the base drive of the pass element and limiting the output current to a safe level.

3.3.32.1.4 +5 Volt Supply

This circuit provides a regulated output of 5 volts at a load current of up to 1.5 amps. In the circuit of Figure 38, Q5 functions as a comparator which compares the output voltage to a reference voltage established by CR2 and the resistor divider network. The output of Q5 controls the driver transistor Q2 which in turn drives the main pass element, Q1. Due to the large amount of power dissipated, the main pass element is mounted on a large heat sink fastened to the DIU chassis.

Overload protection is accomplished by sensing the load current via the voltage drop across R5. Because of the high current involved, a foldback current limiting scheme



is used. The foldback characteristic is produced by R2, R3 and R4, which set the base bias of transistor Q3 just below the output voltage at zero load current.

As the voltage across the current sense resistor R5 increases with increase in load current, the base voltage of Q3 increases to approximately 5.6 volts at which point Q3 conducts and diverts the current supplied by CR1 from Q2. This action causes the output voltage to start to drop. As the load decreases further, Q3 conducts more heavily and the potential across R4 reverses. As the potential across R4 increases, the voltage across R5 will decrease, thus causing the load current to foldback.

Operation of the 5 volt regulator is controlled by the +10 volt, 230 ma supply and the current limiting diode CR1. Removal of the regulated 10 volts will cause the 5 volt regulator to immediately shut off.

3.3.32.1.5 +10 Volt, 230 ma/-10 Volt, 30 ma Supply

The operation and construction is similar to the ± 15 volt supply.

3.3.32.2 Power Supply D (Reference Figure 39)

Output Voltages & Loads	+10 V, 130 ma	-10 V, 8 ma
	+10 V, 140 ma	-10 V, 43 ma
	+10 V, 25 ma	
	+ 5 V, 4.2 amp	
	+ 5 V, 50 ma	
	+15 V, 50 ma	
Input Voltage	24 to 32 VDC	
Ambient Temperature	-55°C to 125°C	
DC Isolation	$>10^8$ ohms input to output	

TABLE VI. POWER SUPPLY D REQUIREMENTS

Due to the similarity between power supply D and power supply A, only the major differences will be discussed.

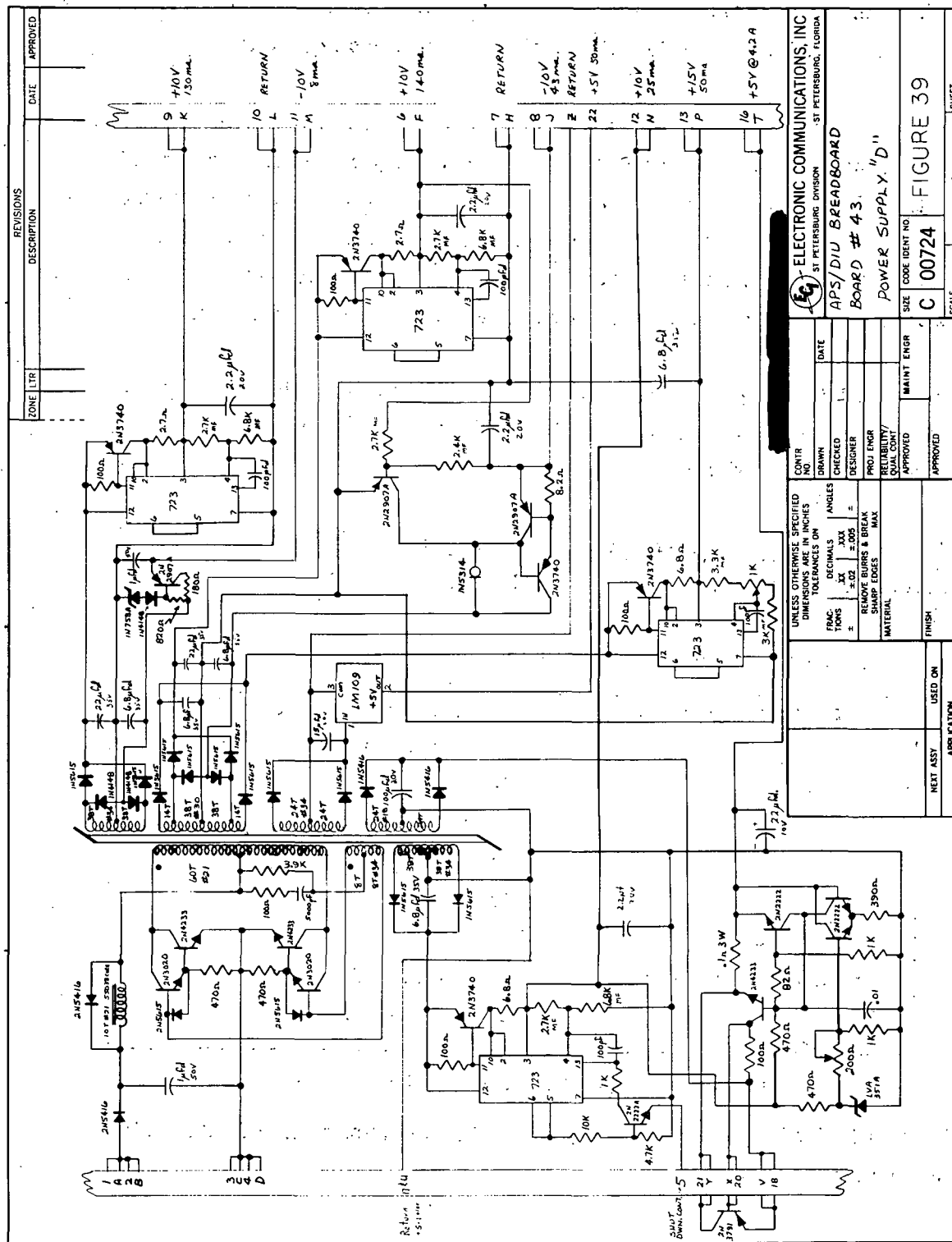


FIGURE 39. POWER SUPPLY "D"



3.3.32.2.1 +10 Volt, 25 ma Supply Shutoff

The operation of the +10 volt supply is controlled by a logic level supplied to pin 5 on the emitter of the 2N2222A transistor. A low level ties the emitter lead to ground and allows the transistor to conduct. This in turn shuts off the regulator. A high level or an open will allow the regulator to function properly. The +10 V regulator in turn controls the 5V, 4.2 amp supply.

3.3.32.2.2 +5 Volt, 50 ma Supply

Since the current requirement on this supply is low, a LM109 was chosen to provide the regulated 5 volts. Current limiting is included to limit the peak output current to a safe value. In addition, thermal shutdown is provided to keep the IC from overheating.

3.4 TEST SET

3.4.1 Functional Description

Figure 40 describes the front panel configuration of the APS/DIU Test Set which is also configured to operate and test the Actuator Interface Digital Interface Unit breadboard presently under construction for NASA.

The Test Set is comprised of two panels; a control panel and a display panel. The control panel sources information to be sent to the APS/DIU as a simulation of the Data Terminal/Data Bus function. The display panel utilizes the outputs of the APS/DIU to display the spark and valve functions, the Status Monitor output words, the Emergency Shutoff Monitor status plus various controls to normalize, fail or input external bridge resistances for the system pressure strain gauges. The remaining displays are Actuator Interface Unit functions which are not to be included in this report.

3.4.1.1 Control Panel

The Control Panel incorporates toggle switches to manually program the Supervisory Word used to feed the APS/DIU when the "MANUAL COMMAND/ENGINE ON-OFF" switch is in the "MANUAL COMMAND" position. The toggle to the right of the Supervisory

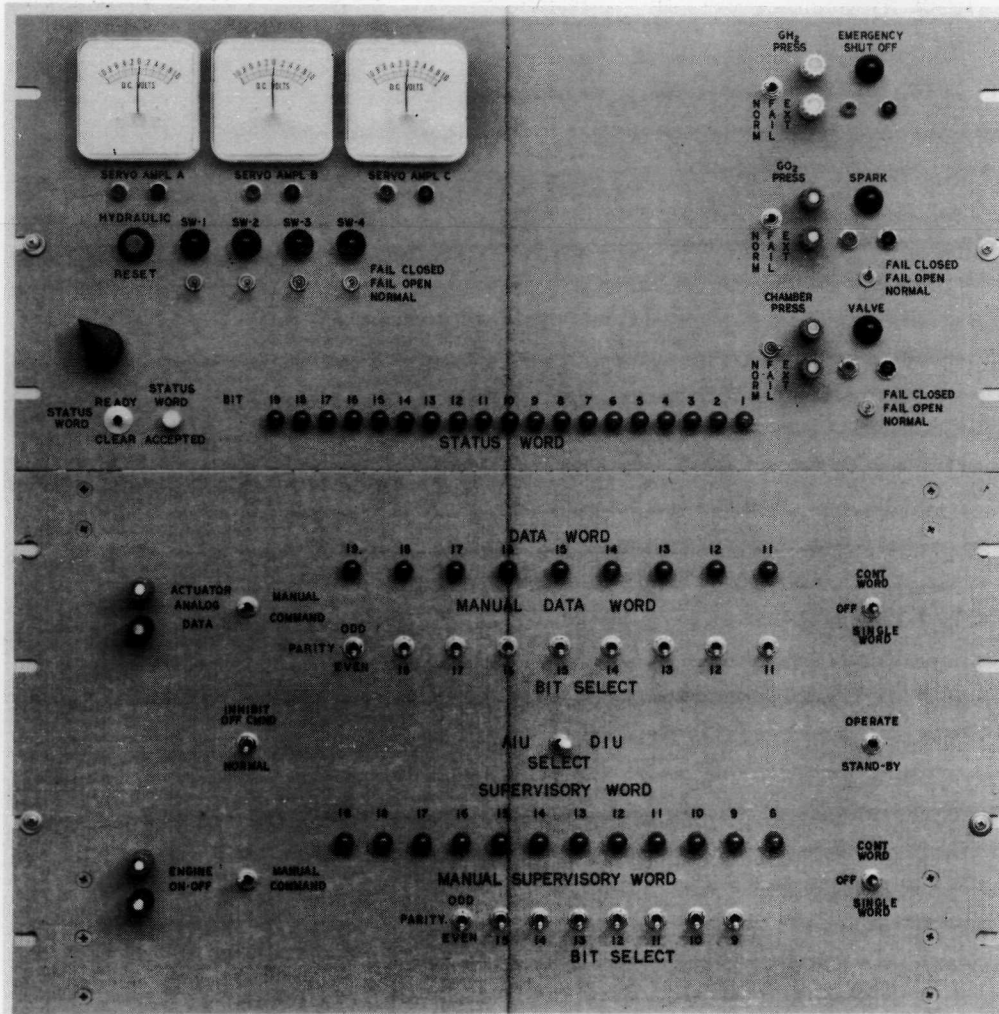


FIGURE 40. APS/DIU - ACTUATOR INTERFACE UNIT
TEST SET



Word set labeled "CONT WORD: OFF: SINGLE WORD" sets the status of the output information. For instance, in the "OFF" position, the Supervisory Word is a continuous 'all-zero' word with odd or even parity programmable with the parity switch at bit 16. The remaining switches do not offer any bit control during this condition. When the toggle is placed in the "CONT WORD" position, the Supervisory Word outputted is that which is programmed (including the parity selected) and the word will exist within each 20 microsecond word frame produced. When the "SINGLE WORD" position is toggled into this momentary position, a single word is issued at the supervisory output in accordance with the program set. After the single word outputs, the Test Set will then continue to output the 'all-zero' word as before.

Now, when the MANUAL COMMAND/ENGINE ON-OFF switch is in the ENGINE ON-OFF position, manual control is inhibited except that either CONT WORD or OFF is programmed. In CONT WORD, the output word is controlled by the ENGINE ON-OFF input. Here, a square-wave generator is used for a signal source where the frequency may be set for repetitious engine firings ie., 1 Hz. In addition, when operating in this ENGINE ON-OFF mode, the "off" command may be inhibited by the switch provided.

The OPERATE/STANDBY switch inhibits all test set functions in the STANDBY mode such that it will output nothing.

3.4.1.2 Display Panel

The panel essentially "closes-the-loop" for the APS/DIU by displaying the outputs available. The EMERGENCY SHUTOFF lamp is illuminated when a Emergency Shutoff Command has been issued on the Control Panel or when the system senses and generates its own ESO condition. The pin jacks provided permit metering the voltage available from the APS/DIU ESO driver. The SPARK lamp illuminates when the Spark Driver is activated within the APS/DIU as does the VALVE lamp. Both the Spark and Valve inputs to the Test Set are appropriately loaded to simulate the system load; 25 ohms for the Spark Driver and 560 ohms for the Valve Driver. Again, pin jacks are provided to measure both the voltage of the drivers as well as the timing. Two additional toggles



are provided to simulate "failure" modes of the Valve and Spark terminations. The Valve may be 'failed' open or closed meaning that the fuel line is closed or opened respectively. The Spark has the same failure provisions of the Display Panel except the APS/DIU does not receive feedback from the Spark High Voltage Supply in the system and, therefore, the APS/DIU will not react to a Spark failure except if its internal driver fails.

Three additional sets of controls are available specifically for the GH2, GO2 and CHAMBER PRESSURE indications to the APS/DIU. Each has an associated toggle switch such that the transducer may be "NORMAL", "FAILED" or simulated "EXT" (externally).

The "NORMAL" position provides a resistance (511 ohms) for the bridge inputs of the APS/DIU Strain Gauge Amplifiers. This value remains fixed during engine-firings for both the GH2 and GO2 line pressures. The resistor is altered, however, for the CHAMBER PRESSURE during engine firings to simulate the generation of chamber pressure. This is done with a relay which adds approximately 12 ohms to the 511 ohms in the bridge load.

The "FAIL" position of these switches alters the bridge such that the amplifiers will cross the failure-detected threshold of approximately 1 volt. In the CHAMBER PRESSURE set, the failure eliminates the capability to simulate 'chamber pressure' during engine firing by keeping the bridge resistance fixed.

The "EXT" position allows utilizing an external decade resistance box for substitution into the bridge. Here, the amplifiers and A/D Converters monitoring these values may be calibrated.

3.4.2 Electrical Design

The modules discussed for the Test Set are assembled on boards similar to those used in the APS/DIU breadboard. All logic components are TTL 7400 devices or comparable



equivalents. The boards are wire-wrapped and the power is supplied by external laboratory bench supplies.

3.4.2.1 Supervisory Word Generator (Figure 41)

This board generates the specific commands to be entered into the word stream feeding the APS/DIU ISVC circuits.

The switches shown at the left of the schematic are used to program the significant bits into the Supervisory Word. This information is multiplexed-selected with the encoded "engine-on" and "engine-off" commands developed automatically by the logic at the lower-left which is fed by a squarewave generator. The ENGINE ON-OFF/MANUAL COMMAND switch controls which data is selected.

The data is loaded into a 20-bit serial register comprised of Fairchild 9300's and is shifted out through a single Polar RZ modulator (75325) to drive the four lines to the APS/DIU. During this shift cycle, the outputted data is detected by a comparator and re-cycled back through the shift register. At the end of each 20-bit 20 microsecond word frame, the information is parallel-shifted into a set of quad "D" storage elements which drive display lamps. This mechanism provides assurance by the lamps that the word that was programmed was outputted through the Polar RZ modulator. The data selected to load into the registers is pre-empted by the 'cycle-control' which disables the multiplexer and enters all zero's into the registers.

3.4.2.2 Timing Logic (Figure 42)

This logic develops the timing and control for the Supervisory Word and the Data Word (employed in the Actuator Interface breadboards).

The logic is configured to generate 20-bit consecutive word frames plus the data frames which are in sync with the Supervisory Word. Further, the register load pulses, Supervisory Cycle Control, A/D Clock (A.I. function), register shift pulses and Polar RZ clock pulses are developed and outputted.



The counters located at C4 and X4 count the 1 MHz clock pulses and the one-shots at D4 generate the reset function after a 20-bit frame has been accumulated. The logic at the top and at the bottom of the schematic is nearly identical to develop the controls of "Continuous Word", "Single Word" or "all-zero" words (off) for both the Supervisory and Data sections.

Figure 43 describes the timing and signals generated.

3.4.2.3 Display Panel Status Monitor (Figure 44)

The function of this circuit is to accept single words from the APS/DIU (or A.I.) and store and display the word information in 19 bits.

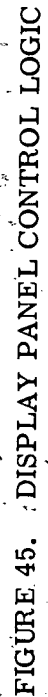
The data is received on four pair (schematic left) and line-selected by a rotary switch. The line is then transformer coupled into a pair of comparators used as line receivers to recover the clock from the data. The data is outputted from comparator E1 and is fed to the shift register comprised of Fairchild 9300's. The two one-shots at A1 are used to develop the register shift clock (125 nsec) and the "end-of-word" pulse (1.25 μ sec). The end-of-word pulse loads the storage elements which feeds the lamp drivers.

A latch is shown (upper left), at location X2, which is used to recognize and drive a lamp indicating that a 19-bit word has been received and accepted. The purpose of this added lamp is to inform the operator that an "all zero" word has been received as opposed to the Test Set receiving an "all-zero" word without any indications of activity. A reset switch is provided to clear this latch.

3.4.2.4 Display Panel Control Logic (Figure 45)

This board serves two functions:

- (1) provide simulated hydraulic switching to close-the-loop on the Actuator Interface Breadboard, and
- (2) provide both a load and display for the APS/DIU as well as pressure sensor simulation.





The A. I. U. portion of this board will not be discussed in this report.

The right side of the schematic details the hardware used exclusively for the APS/DIU. The Valve Drive is shown inputted on pins L and M of connector 3 and driving a relay B2. The load presented by this relay is 40 to 50 ma so no additional load resistor is included. The contacts of this relay are used to feed through the "failure" switch SW11. This switch is tied to the valve lamp as well as relay B4. A pair of contacts are brought out from B4 to simulate the "Valve Switch" requirements of the APS/DIU. In addition, another pair of contacts are placed across a 12 ohm resistor such that the resistance increases during valve activity.

The Spark input also drives a relay but, in addition, a 25 ohm resistor is across the relay to raise the driver load current to 1 amp. The Emergency Shutoff Monitor is also fed to a relay. The relays for both the Spark and ESO drivers are used to illuminate lamps.

A contributing asset derived from the use of relays (with diode protection) is the inherent delay in turning them on and off. This delay somewhat simulates the delays that may be experienced in driving the actual valves.

3.4.2.5 Actuator Interface Breadboard Test Set Modules

The remainder of the Test Set functional modules are utilized exclusively for testing the Actuator Interface Breadboard(s) and will not be discussed in this report. They are included only for information purposes.

Figure 46: Clock Generator and A/D Converter

Figure 47: A. I. U. Data Generator

Not Included: Analog Mathematical Model



4.0 CONCLUSIONS AND RECOMMENDATIONS

4.1 SYSTEM PERFORMANCE

The breadboard system generally performed as was originally intended in the proposal concept with few design deviations. Because the design was oriented toward a "final product" in LSI format, the designs of several areas became more complex than that which would have resulted from a "minimum hardware" approach. Some design areas are merely 'go-as-is' circuits; that is, the implementation into LSI is virtually an immediate conversion from the operational schematics. Other areas require modification or minor changes in concept for more efficient implementation; this was proven by the breadboard effort.

Making this breadboard perform yielded several ideas. First, it proved that the dual-failure immunity concept is complex. Yet it is not so complex to make if impractical to implement. Even to the extent that it was implemented in the APS/DIU where it manages its own redundancy. Second; the breadboard demonstrated two types of redundancy philosophies; four-wide and three-wide. Here, the four-wide circuits perform identically and in parallel as in the ISVC circuits. Failure immunity is achieved by a complex of inter-voters to compare-out the errors. The three-wide operates singly and individually. A single function, as in the Firing Logic set, implements sufficient circuitry to determine its own validity. And, when it fails, it powers up an identical backup to perform the same function.

Both techniques have their merit; both performed well. Both required added hardware; both are difficult to test. Yet, together they complement the requirements of functional performance, minimum density and minimum power requirements.

4.2 DESIGN CONSIDERATIONS

As proven out in the breadboard system, the circuit designs operate. However, some circuits are basically inadequate or over-designed and, although this has been recognized, no additional time was consumed to re-arrange these designs.



It is the function of a breadboard program to point out deficiencies and, unless the problem is major, they usually need not be corrected as long as the 'fix' is operational and the problem is clearly identified.

These areas will be discussed in this section.

4.2.1 Line Receiver/Photo-Isolator Interface Circuit (Reference Figure 11)

The function of this circuit is to provide an isolated interface between the input lines and the APS/DIU processing circuits. The purpose of designing a photo-isolator interface was that, in micro-min technology, it could conceivably be packaged in less volume than a transformer plus its related circuitry. This may still be true; however, the circuit that resulted during the breadboard program became necessarily complex such that it would perform over temperature, and, its power requirements are high. The MCD-4 photo-isolator diode works over temperature provided that it is driven hard (160 ma each) and the recovery circuits required to re-establish the data are complex and consume considerable power. Consequently, the circuit is considered too complex for the function that it performs; and, since it is a "power-hog" it is doubtful that it could be efficiently micro-miniaturized considering the heat that has to be removed.

Conclusively, the photo-isolator technique should be shelved until more efficient devices are available and the circuit should be replaced with a pulse transformer coupler, as shown in Figure 48. The volume of the transformer can be small and its associated circuitry can be hybridized. The end volume consumed would probably be less than that required to produce the photo-isolated unit plus the power supply required to support it.

4.2.2 Power Enable/Disable Logic (Reference Figures 16, 17 and 18)

The logic in these functions is triplex/majority-voted to an output set of quad transistors and parallel transistors used as switches to 'turn-on' or 'ground' the power to the Firing Logic. This circuit can be considerably simplified using a set of buffer/drivers to control the power switching instead of transistors. The power requirements of the Firing Logic is considerably less than is presently deliverable.

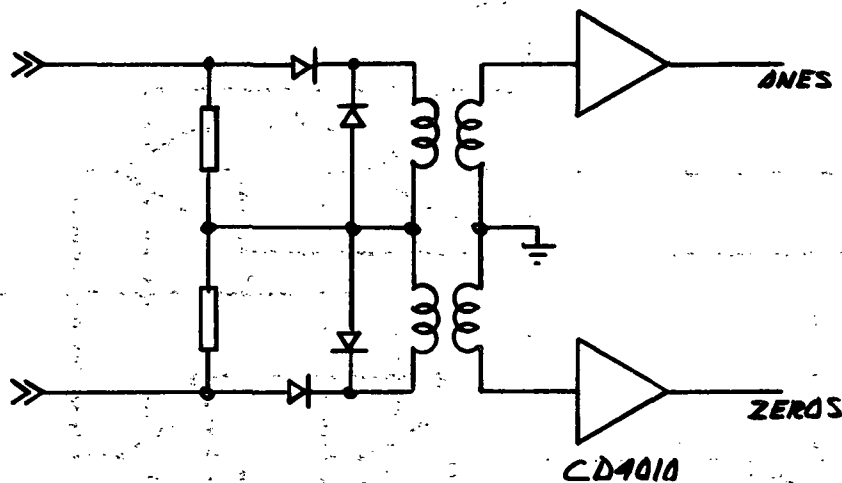


FIGURE 48. POLAR RZ LINE RECEIVER INTERFACE.

The original design was intended to open both the power and ground paths to the Firing Logic. However, because of the input protective circuits employed in CMOS gates, the results of opening the power lines was to output the input signals from the Firing Logic. The logic became a resistive pass-element and mixed the input signals to any single output. Consequently, the only way to completely disable this logic was to resistively isolate each input and ground the power line.

The Power Enable/Disable Logic was then modified to generate either a +10 volt or a ground to the Firing Logic power line. Much of the circuitry incorporated became unnecessary, but was left in.

Figure 49 illustrates this output circuit for the Power Enable/Disable.

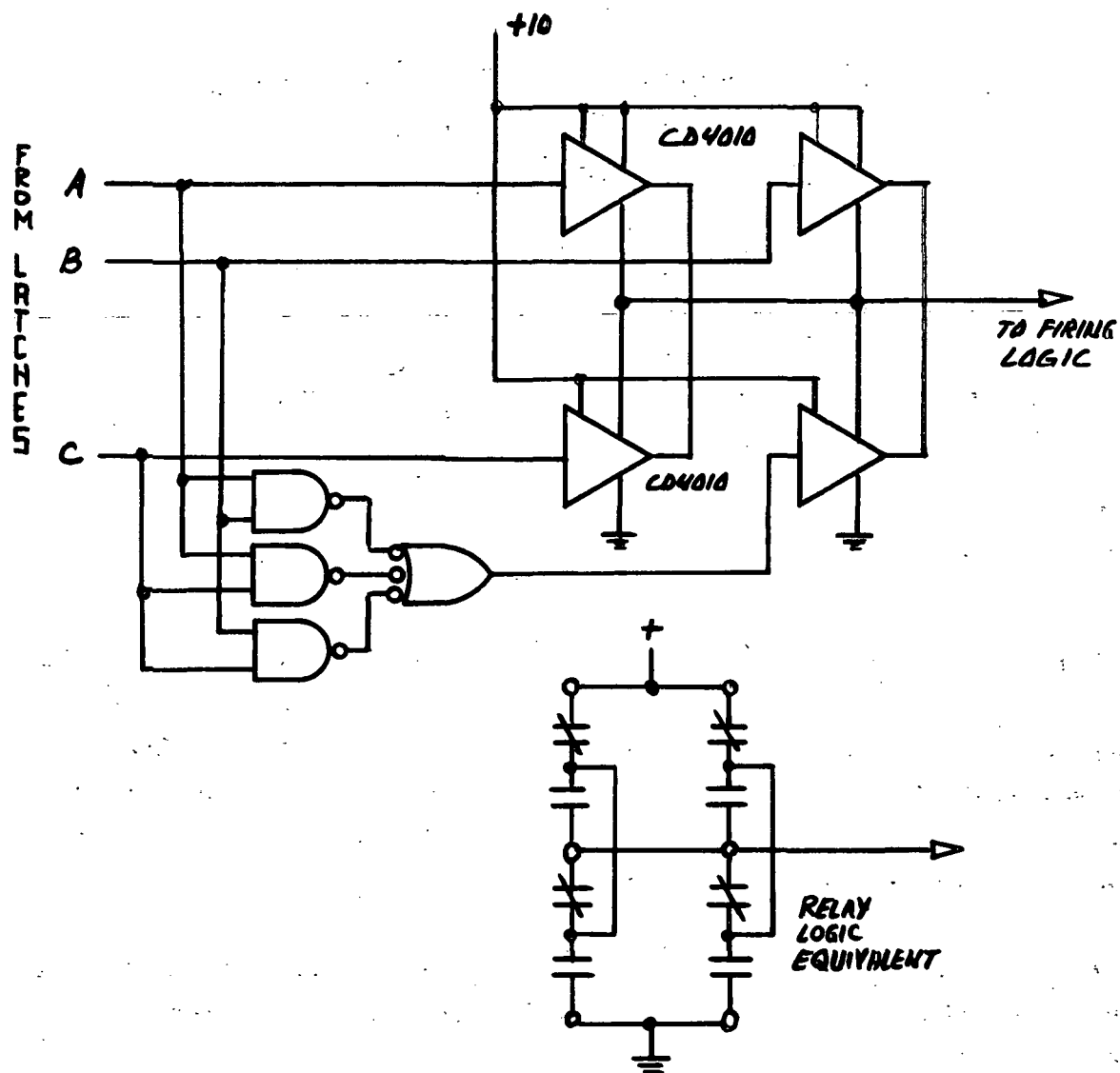


FIGURE 49. SUBSTITUTE POWER ENABLE/DISABLE DRIVER



4.2.3 Test Sequencer; (Reference Figures 28 through 35)

4.2.3.1 TTL versus CMOS Implementation

The circuits designed and fabricated for the Test Sequencer were done, in part in TTL as opposed to CMOS. During the design effort, several areas had to remain flexible so that during system test the functions of the Test Sequencer could easily be updated if necessary. Consequently, TTL was employed in the timing and control sections because of its convenience and availability.

In the final configuration, the Test Sequencer would be implemented in CMOS/LSI because its design has been virtually finalized. Again, the breadboard proved out the feasibility of the technique and the direction has been defined for the final package.

4.2.3.2 Philosophy of Data Formulation

Presently, the Test Sequencer is configured to output an "all-zero" word if all functions perform correctly or a pattern of one's, some of which are 2-bit codes identifying probable if not specific, failed area. Two significant changes are recommended in this area:

- (1) At the initiation of the 'self-test' a reset pulse is issued to fix the recording latches to a 'zero' state and then as failed information is collected, it is used to set the latches to the 'one' state. After this scheme had been implemented, it became obvious that this initiation method and collection method is inverse of the ideal process. That is, the reset pulse should fix the latches to an all 'one' state (the failed state) and as good information is collected, the latches are set to the 'zero' state. Here, it takes correct logical activity to recognize "good" performance rather than inactivity implying "good" operation and activity recognizing "failed" data. An examination of the system shows several areas where a Test Sequencer gate could fail and the resultant outputted information would indicate that the tested operation was valid. The Test Sequencer operation would not be suspect until the system itself did not perform as well as the Test Sequencer indicated it should.



- (2) Another area which should be considered for design alteration is the bit scheme used to indicate the test results. Presently, the outputted 16-bit word is a direct readout of several tests; some single bits assigned for "go-no" of a specific section or a two-bit code indicating such things as "A is bad; B is bad, or both A and B are bad, or C is bad." These two-bit schemes depend somewhat on the probability of catastrophe and are really insufficient as a measure of the system performance. It is recommended, therefore, that an encoding scheme be devised to take advantage of the 2^{16} possible combinations that could exist for the 'self-test' report.

4.2.3.3 Test Sequencer Tests 13 through 15

The intent of these three tests was to validate the automatic switch-over capability from Firing Logic "A" to "B" to "C" and then off. The sequence would depend on the Function Monitors to recognize that the engine was not responding to the Firing Logic commands (they were inhibited) and would therefore shut down their associated set and cause turn-on of the backup.

Once the system had been assembled and operating, it was recognized that this function did not work as a process of the Test Sequencer. The control memory function of the Test Sequencer has "hard control" of the various APS/DIU functions including the Power Enable/Disable Logics as it sequences through the various tests. That is, it will force a circuit on or force it off and it will hold that given state until the reverse is required. This hard-control has to be released during tests 13 through 15 but maintained for the earlier tests. For instance, at the beginning of test 13, Logic Set "A" has to be turned on such that the Function Monitor can turn it off when it recognizes the 'failure.' The Control Memory, however, holds it 'on' continually and therefore the Function Monitor 'turnoff' activity is not recognized nor is the backup logic "B" turned 'on' since it too is held off by the memory.

Because this problem emerged at the time that the unit was due to be delivered to NASA, a redesign was not undertaken to fix this test although the method for doing so is



recognized and the modifications will be added if NASA requires it in the breadboard.

First, two "test enable" and test disable" inputs have to be configured to each of the Power Enable/Disable boards "A", "B" and "C". One of these sets would be used for the 'hard-control' requirements and the other would be considered 'soft-control' where the required configuration is capacitively pulsed at the beginning of the test and control released throughout the test. Here, for instance, Power Enable/Disable "A" would be pulsed "on" at the beginning of test 13 prior to the issuance of the "engine-on" command. Power Enable/Disable sets "B" and "C" would be pulsed "off" at this same time. Then the logics would be free to act among themselves and the results measured. At the beginning of test 14 "B" would be pulsed 'on and "A" and "C" would be pulsed "off" prior to the "engine-on" command. Again, the logics would be free to act among themselves and the results measured. A similar process would be exercised for test 15.

4.2.3.4 Power Supplies and Power Consumption

The system breadboard consumes approximately sixty watts in its present configuration which is considerably higher than necessary. The power supplies are designed to supply this energy for the breadboard. In the final configuration, with all circuits LSI and/or hybridized and with the TTL elements minimized, it is estimated that the power requirements will be less than 10 watts maximum. This means a considerable reduction in the volume requirements for the power supplies (although the same design philosophy will be followed) and less heat to remove.

The circuits adjusted for reduced power would be the Line Receiver (transformer coupling instead of photo-isolation), the Power Enable/Disable Logic, the Test Sequencer (CMOS instead of TTL), and the Power Interrupt circuits which are designed to switch heavier loads than will be required.



4.3 LSI IMPLEMENTATION

The next step in the APS/DIU development would be the manufacture of LSI prototype models using CMOS/LSI and hybrid techniques for the non-digital circuitry. Because the chip manufacturing technique yields multiple chips for each single run, the prototype fabrication would, in fact, yield approximately 20 models for the cost of one.

4.3.1 Implementation Procedures

The system would first be partitioned into areas that operate from a common supply with a minimum I/O count plus maximum device count. Specifications would be rigidly defined for the function(s) such that the logic diagram may be computer verified for functional validity. At this time, revisions may be programmed to improve response, propagation delay, etc., and this also will be computer-verified as well as generate updates in the logic diagrams.

Once the functional diagrams have been idealized, the design is ready for layout. Here, the "cells" are compiled from the library of devices presently available to generate the functions required. Computer layout may be used exclusively or it may be complemented with additional hand layout to maximize the density if the particular chip design is crowded.

Once the layout is complete, the photo artwork is generated to create the masks required. Then the wafers are exposed and the processes of diffusion, oxidation and metalization are performed as required. Several tests are performed on the wafers as they are produced to verify their operational characteristics and then they are packaged in multi-pin flat packs or just dices for chip-and-wire bonding to other devices on a substrate.

The processes briefly outlined here are shown in Figure 50, in block diagram form.

4.3.2 LSI Implementation Program Requirements

A typical turn-around time for chip production is approximately 60 days, given 30 days for design and thirty days for prototype production. However, several tasks must be

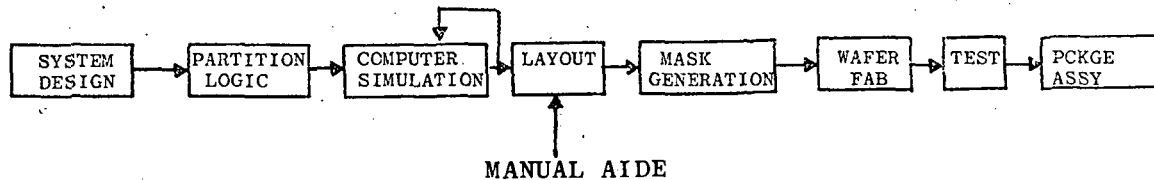


FIGURE 50. LSI PROTOTYPE PROCESS FLOW DIAGRAM

accomplished prior to the design of any chips. A brief list of these tasks are as follows:

- (1) Firm systems definition on I/O; word format, codes, etc.
- (2) Firm definition on valve and spark requirements.
- (3) Firm definition on sensor format; valve switches, pressure sensors, etc.
- (4) Revision and update on certain circuit designs and procedures outlined in this report.
- (5) Firm definition of package goal; (64 in³).
- (6) Partitioning of the APS/DIU circuitry to minimum number of chips with maximum density and compatible I/O.
- (7) Partitioning and layout of hybrid micro-miniaturized circuitry.

After these items have been covered, chip design may begin. Once the chips are available and the hybrid hardware has been layed out, the first prototypes may be assembled.

As a budgetary time estimate, ECI feels that a one-year program is a reasonable goal to produce several prototypes following firm systems definition.